

## Stepping Motor Driver series



# High Performance, High Reliability 36V Series Stepping Motor Drivers

## BD63877/BD63875/BD63873EFV (CLK-IN type) BD63876/BD63874/BD63872EFV (PARALLEL-IN type)

### Outline

BD6387 EFV series are the high-grade type that provides the highest function and highest reliance in the ROHM stepping motor driver series.

As for its basic function, it is a low power consumption bipolar PWM constant current-drive driver with power supply rated voltage of 36V and rated output current (DC) of 1.0A, 1.5A, 2.0A. For the input interface, BD63877/BD63875/BD63873EFV are CLK-IN type drivers and BD63876/BD63874/BD63872EFV are PARALLEL-IN type drivers. There are excitation modes of FULL STEP & HALF STEP (2 kinds), QUATER STEP mode, and for current decay mode, the ratio of FAST DECAY & SLOW DECAY can be freely set, so the optimum control conditions for every motor can be realized. In addition, being able to drive with one system of power supply makes contribution to the set design's getting easy.

### Feature

- 1) Single power supply input (rated voltage of 36V)
- 2) Rated output current:(DC) 1.0A, 1.5A, 2.0A
- 3) Low ON resistance DMOS output
- 4) CLK-IN drive mode (BD63877/63875/63873EFV)
- 5) PARALLEL-IN drive mode (BD63876/63874/63872EFV)
- 6) PWM constant current control (other oscillation)
- 7) Built-in spike noise cancel function (external noise filter is unnecessary)
- 8) Full-, half (two kinds)-, quarter-step functionality
- 9) Current decay mode switching function (linearly variable FAST/SLOW DECAY ratio)
- 10) Normal rotation & reverse rotation switching function (BD63877/63875/63873EFV)
- 11) Power save function
- 12) Built-in logic input pull-down resistor
- 13) Power-on reset function (BD63877/63875/63873EFV)
- 14) Thermal shutdown circuit (TSD)
- 15) Over current protection circuit (OCP)
- 16) Under voltage lock out circuit (UVLO)
- 17) Over voltage lock out circuit (OVLO)
- 18) Ghost Supply Prevention (protects against malfunction when power supply is disconnected)
- 19) Electrostatic discharge: 8kV (HBM specification)
- 20) Adjacent pins short protection
- 21) Inverted mounting protection
- 22) Microminiature, ultra-thin and high heat-radiation (exposed metal type) HTSSOP-B28 package
- 23) Pin-compatible line-up (BD63877/63875/63873EFV, BD63876/63874/63872EFV)

### Application

PPC, multi-function printer, laser beam printer, ink jet printer, monitoring camera, WEB camera, sewing machine, photo printer, FAX, scanner, mini printer, toy, and robot etc.

Absolute maximum ratings(Ta=25 )

Item	Symbol	BD63877/63876EFV	BD63875/63874EFV	BD63873/63872EFV	Unit
Supply voltage	V <sub>CC1,2</sub>	-0.2 ~ +36.0			V
Power dissipation	Pd	1.45 <sup>1</sup>			W
		4.70 <sup>2</sup>			W
Input voltage for control pin	V <sub>IN</sub>	-0.2 ~ +5.5			V
RNF maximum voltage	V <sub>RNF</sub>	0.7			V
Maximum output current	I <sub>OUT</sub>	2.0 <sup>3</sup>	1.5 <sup>3</sup>	1.0 <sup>3</sup>	A/phase
Maximum output current (PEAK) <sup>4</sup>	I <sub>OUTPEAK</sub>	2.5 <sup>3</sup>	2.0 <sup>3</sup>	1.5 <sup>3</sup>	A/phase
Operating temperature range	T <sub>opr</sub>	-25 ~ +85			
Storage temperature range	T <sub>stg</sub>	-55 ~ +150			
Junction temperature	T <sub>jmax</sub>	+150			

<sup>1</sup> 70mm × 70mm × 1.6mm glass epoxy board. Derating in done at 11.6mW/ for operating above Ta=25 .

<sup>2</sup> 4-layer recommended board. Derating in done at 37.6mW/ for operating above Ta=25 .

<sup>3</sup> Do not, however exceed Pd, ASO and Tjmax=150 .

<sup>4</sup> Pulse width tw 1ms, duty 20%.

Operating conditions(Ta= -25 ~ +85 )

Item	Symbol	BD63877/63876EFV	BD63875/63874EFV	BD63873/63872EFV	Unit
Supply voltage	V <sub>CC1,2</sub>	19~28			V
Maximum Output current (DC)	I <sub>OUT</sub>	1.7 <sup>5</sup>	1.2 <sup>5</sup>	0.7 <sup>5</sup>	A/phase

<sup>5</sup> Do not, however exceed Pd, ASO and .

Electrical characteristics (Unless otherwise specified Ta=25 , V<sub>CC1,2</sub>=24V)

Item	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Whole						
Circuit current at standby	I <sub>CCST</sub>	-	1.0	2.5	mA	PS=L
Circuit current	I <sub>CC</sub>	-	2.5	5.0	mA	PS=H, VREF=3V
Control input						
H level input voltage	V <sub>INH</sub>	2.0	-	-	V	
L level input voltage	V <sub>INL</sub>	-	-	0.8	V	
H level input current	I <sub>INH</sub>	35	50	100	μA	V <sub>IN</sub> =5V
L level input current	I <sub>INL</sub>	-10	0	-	μA	V <sub>IN</sub> =0V
Output (OUT1A, OUT1B, OUT2A, OUT2B)						
Output ON resistance (BD63877/63876EFV)	R <sub>ON</sub>	-	0.65	0.85		I <sub>OUT</sub> =1.5A, Sum of upper and lower
Output ON resistance (BD63875/63874EFV)	R <sub>ON</sub>	-	1.00	1.30		I <sub>OUT</sub> =1.0A, Sum of upper and lower
Output ON resistance (BD63873/63872EFV)	R <sub>ON</sub>	-	1.90	2.47		I <sub>OUT</sub> =0.5A, Sum of upper and lower
Output leak current	I <sub>LEAK</sub>	-	-	10	μA	
Current control						
RNFXS input current	I <sub>RNFS</sub>	-2.0	-0.1	-	μA	RNFXS=0V
RNFX input current	I <sub>RNF</sub>	-40	-20	-	μA	RNFX=0V
VREF input current	I <sub>VREF</sub>	-2.0	-0.1	-	μA	VREF=0V
VREF input voltage range	V <sub>REF</sub>	0	-	3.0	V	
MTH input current	I <sub>MTH</sub>	-2.0	-0.1	-	μA	MTH=0V
MTH input voltage range	V <sub>MTH</sub>	0	-	3.5	V	
Minimum on time (Blank time)	t <sub>ONMIN</sub>	0.3	0.8	1.5	μs	C=1000pF, R=39k
BD63877EFV/63875EFV/63873EFV						
Comparator threshold	V <sub>CTH</sub>	0.57	0.60	0.63	V	VREF=3V
BD63876EFV/63874EFV/63872EFV						
Comparator threshold 100%	V <sub>CTH100</sub>	0.57	0.60	0.63	V	VREF=3V, (I0X,I1X)=(L,L)
Comparator threshold 67%	V <sub>CTH67</sub>	0.38	0.40	0.42	V	VREF=3V, (I0X,I1X)=(H,L)
Comparator threshold 33%	V <sub>CTH33</sub>	0.18	0.20	0.22	V	VREF=3V, (I0X,I1X)=(L,H)

Input output equivalent circuit diagram

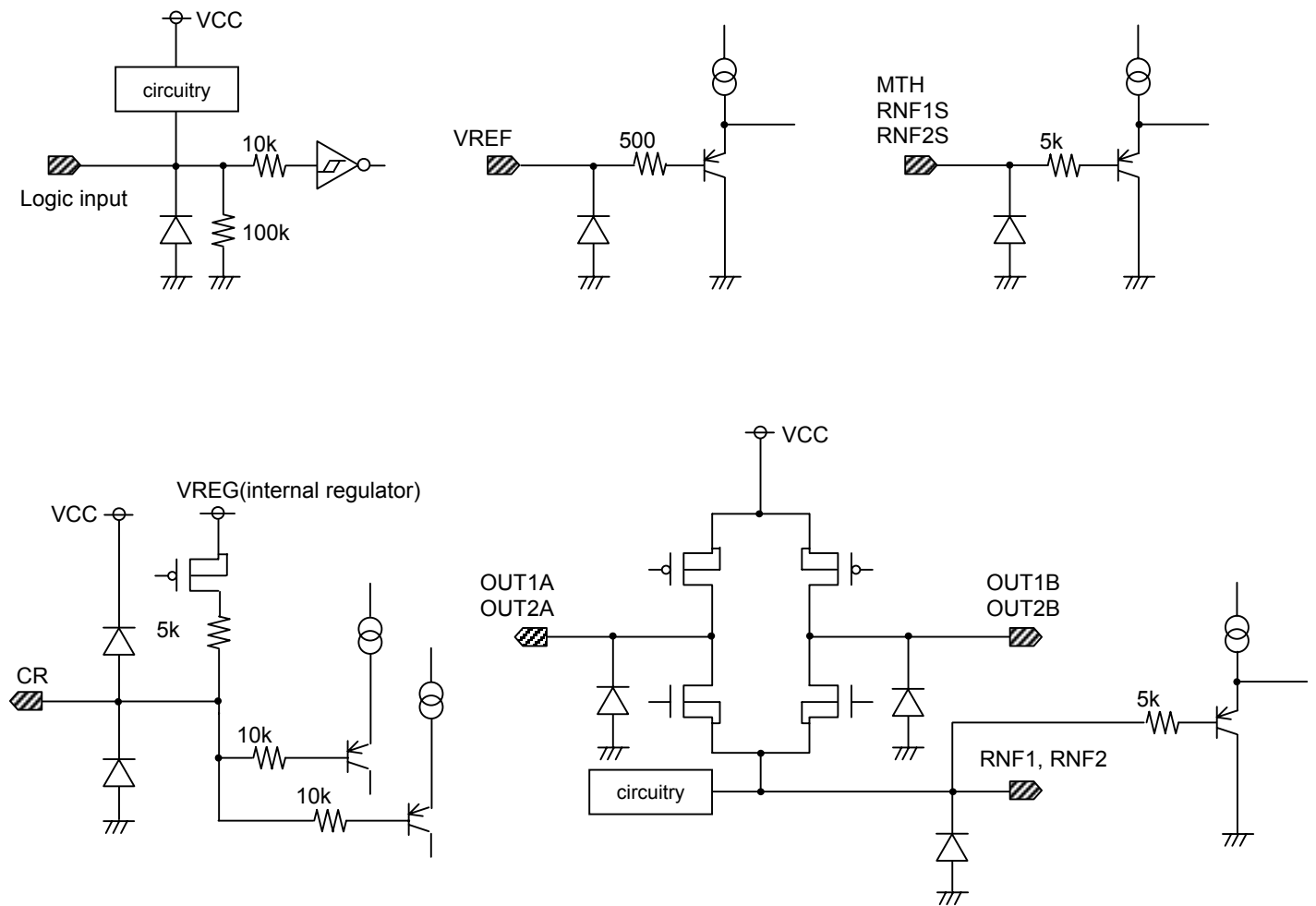


Fig.1 Input output equivalent circuit diagram

Terminal function and Application circuit diagram  
CLK-IN type (BD63877/63875/63873EFV)

Pin No.	Pin name	Function	Pin No.	Pin name	Function
1	GND	Ground terminal	15	CLK	Clock input terminal for advancing the electrical angle.
2	OUT1B	H bridge output terminal	16	CW_CCW	Motor rotating direction setting terminal
3	RNF1	Connection terminal of resistor for output current detection	17	TEST	Terminal for testing (used by connecting with GND)
4	RNF1S	Input terminal of current limit comparator	18	MODE0	Motor excitation mode setting terminal
5	OUT1A	H bridge output terminal	19	MODE1	Motor excitation mode setting terminal
6	NC	Non connection	20	ENABLE	Power supply terminal
7	VCC1	Power supply terminal	21	NC	Non connection
8	NC	Non connection	22	VCC2	Power supply terminal
9	GND	Ground terminal	23	NC	Non connection
10	CR	Connection terminal of CR for setting chopping frequency	24	OUT2A	H bridge output terminal
11	NC	Non connection	25	RNF2S	Input terminal of current limit comparator
12	MTH	Current decay mode setting terminal	26	RNF2	Connection terminal of resistor for output current detection
13	VREF	Output current value setting terminal	27	OUT2B	H bridge output terminal
14	PS	Power save terminal	28	NC	Non connection

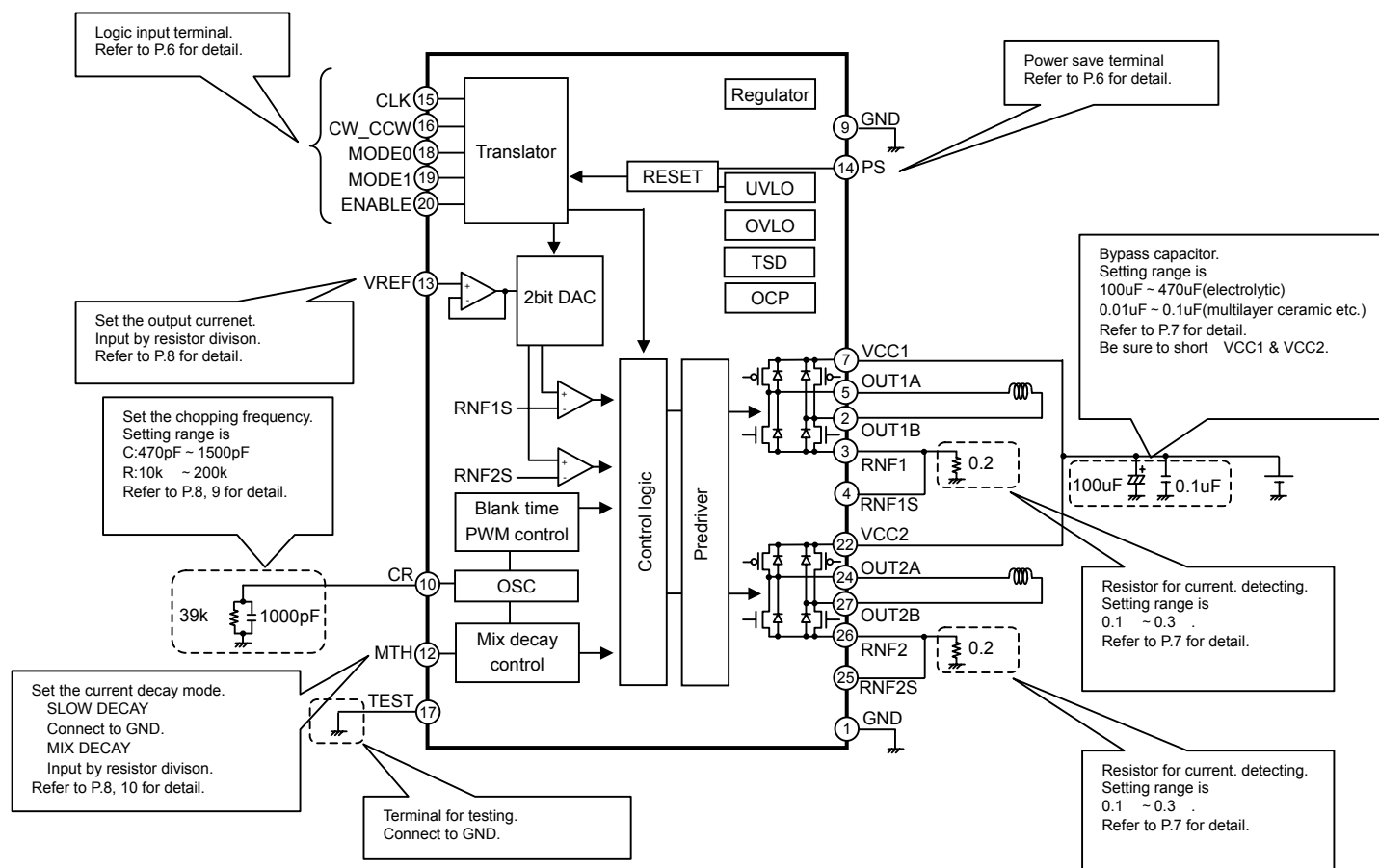


Fig.2 Block diagram & Application circuit diagram of BD63877EFV/BD63875EFV/BD63873EFV

# PARALLEL-IN type (BD63876/63874/63872EFV)

Pin No.	Pin name	Function	Pin No.	Pin name	Function
1	GND	Ground terminal	15	PHASE1	Phase selection terminal
2	OUT1B	H bridge output terminal	16	I01	VREF division ratio setting terminal
3	RNF1	Connection terminal of resistor for output current detection	17	I11	VREF division ratio setting terminal
4	RNF1S	Input terminal of current limit comparator	18	PHASE2	Phase selection pin
5	OUT1A	H bridge output terminal	19	I02	VREF division ratio setting terminal
6	NC	Non connection	20	I12	VREF division ratio setting terminal
7	VCC1	Power supply terminal	21	NC	Non connection
8	NC	Non connection	22	VCC2	Power supply terminal
9	GND	Ground terminal	23	NC	Non connection
10	CR	Connection terminal of CR for setting chopping frequency	24	OUT2A	H bridge output terminal
11	NC	Non connection	25	RNF2S	Input terminal of current limit comparator
12	MTH	Current decay mode setting terminal	26	RNF2	Connection terminal of resistor for output current detection
13	VREF	Output current value setting terminal	27	OUT2B	H bridge output terminal
14	PS	Power save terminal	28	NC	Non connection

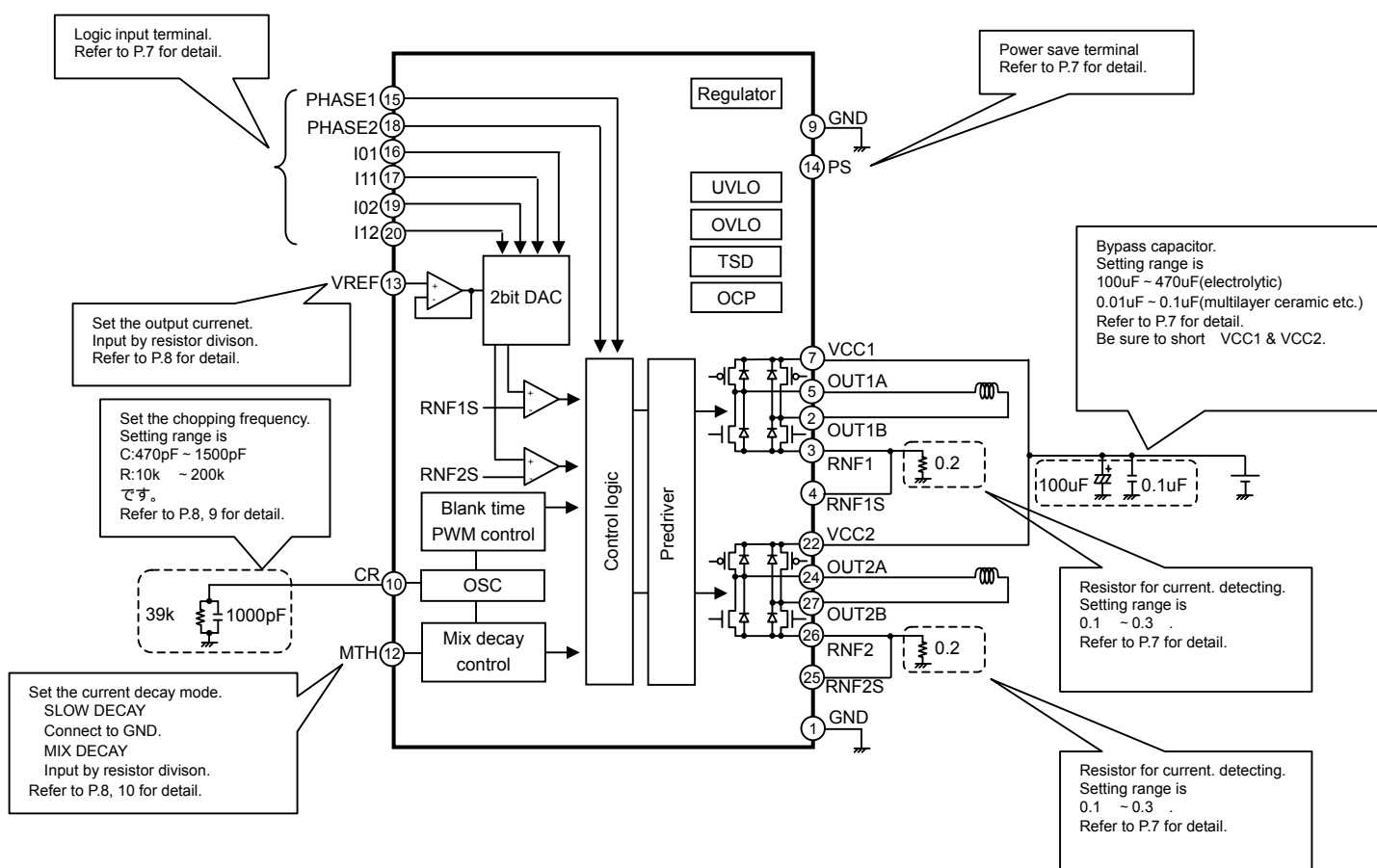


Fig.3 Block diagram & Application circuit diagram of BD63877EFV/BD63875EFV/BD63873EFV

Points to notice for terminal description and PCB layout

CLK / Clock input terminal for advancing the electrical angle(BD63877/BD63875/BD63873EFV)

CLK is reflected at rising edge. The Electrical angle advances by one for each CLK input.

Motor's misstep will occur if noise is picked up at the CLK terminal, so please design the pattern in such a way that there is no noise plunging.

MODE0,MODE1 / Motor excitation mode setting terminal (BD63877/BD63875/BD63873EFV)

Set the motor excitation mode.

MODE0	MODE1	Excitation mode
L	L	FULL STEP
H	L	HALF STEP A
L	H	HALF STEP B
H	H	QUARTER STEP

Please refer to the P.12, 13 for the timing chart & motor torque vector of various excitation modes.

Unrelated to CLK, change in setting is forcibly reflected (refer to P.16).

CW CCW Terminal / Motor rotating direction setting terminal (BD63877/BD63875/BD63873EFV)

Set the motor's rotating direction. Change in setting is reflected at the CLK rising edge immediately after the change in setting (refer to P.14)

CW CCW	Rotating direction
L	Clockwise (CH2's current is outputted with a phase lag of 90 ° in regard to CH1's current)
H	Counter Clockwise(CH2's current is outputted with a phase lead of 90 ° in regard to CH1's current)

ENABLE Terminal / Output enable terminal (BD63877/BD63875/BD63873EFV)

Turn off forcibly all the output transistors (motor output is open).

At the time of ENABLE=L, electrical angle or operating mode is maintained even if CLK is inputted.

Please be careful because the electrical angle at the time of ENABLE being released (ENABLE=L H) is different from the released occasion at the section of CLK=H and from the released occasion at the section of CLK = L (refer to P.15).

ENABLE	Motor output
L	OPEN (electrical angle maintained)
H	ACTIVE

PS / Power save terminal (BD63877/BD63875/BD63873EFV)

PS can make circuit standby state and make motor output OPEN. In standby state, translator circuit is reset (initialized) and electrical angle is initialized.

Please be careful because there is a delay of 40μs(max.) before it is returned from standby state to normal state and the motor output becomes ACTIVE (refer to P.11).

PS	State
L	Standby state (RESET)
H	ACTIVE

The electrical angle (initial electrical angle) of each excitation mode immediately after RESET is as follows (refer to P.12, 13).

Please be careful because the initial state at the time of FULL STEP is different from those of other excitation modes.

Excitation mode	Initial electrical angle
FULL STEP	45 °
HALFSTEP A	0 °
HALFSTEP B	0 °
QUARTER STEP	0 °

TEST Terminal / Terminal for testing (BD63877/BD63875/BD63873EFV)

This is the terminal used at the time of shipping test. Please connect to GND. Please be careful because there is a possibility of malfunction if GND unconnected.

PS / Power save terminal (BD63876/63874/63872EFV)

PS can make circuit standby state and make motor output OPEN. Please be careful because there is a delay of 40μs(max.) before it is returned from standby state to normal state and the motor output becomes ACTIVE.

PS	State
L	Standby state (RESET)
H	ACTIVE

#### PHASE1,PHASE2 / Phase selection terminal (BD63876/63874/63872EFV)

These terminals determine output state.

PHASE1	PHASE2	OUT1A	OUT1B	OUT2A	OUT2B
L	L	L	H	L	H
H	L	H	L	L	H
L	H	L	H	H	L
H	H	H	L	H	L

#### I01,I02,I11,I12 / VREF division ratio setting terminal (BD63876/63874/63872EFV)

These terminals determine internal 2bit-DAC output voltage for current limit.

I0X	I1X	Output current level(%)
L	L	100
H	L	67
L	H	33
H	H	0

(I0X, I1X)=(H, H): motor output are open.

#### VCC1,VCC2 / Power supply terminal

Motor's drive current is flowing in it, so please wire in such a way that the wire is thick & short and has low impedance. Voltage VCC may have great fluctuation, so please arrange the bypass capacitor of about 100  $\mu$  ~ 470  $\mu$  F as close to the terminal as possible and adjust in such a way that the voltage VCC is stable. Please increase the capacity if needed especially when a large current is used or those motors that have great back electromotive force are used. In addition, for the purpose of reducing of power supply's impedance in wide frequency bandwidth, parallel connection of multi-layered ceramic capacitor of 0.01  $\mu$  ~ 0.1  $\mu$  F etc is recommended. Extreme care must be used to make sure that the voltage VCC does not exceed the rating even for a moment. VCC1 & VCC2 are shorted inside IC, so please be sure to short externally VCC1 & VCC2 when using. If used without shorting, malfunction or destruction may occur because of concentration of current routes etc., so please make sure that they are shorted when in use. Still more, in the power supply terminal, there is built-in clamp component for preventing of electrostatic destruction. If steep pulse or voltage of surge more than maximum absolute rating is applied, this clamp component operates, as a result there is the danger of destruction, so please be sure that the maximum absolute rating must not be exceeded. It is effective to mount a Zener diode of about the maximum absolute rating. Moreover, the diode for preventing of electrostatic destruction is inserted between VCC terminal and GND terminal, as a result there is the danger of IC destruction if reverse voltage is applied between VCC terminal and GND terminal, so please be careful.

#### GND / Ground terminal

In order to reduce the noise caused by switching current and to stabilize the internal reference voltage of IC, please wire in such a way that the wiring impedance from this terminal is made as low as possible to achieve the lowest electrical potential no matter what operating state it may be.

#### OUT1A,OUT1B,OUT2A,OUT2B / H Bridge output terminal

Motor's drive current is flowing in it, so please wire in such a way that the wire is thick & short and has low impedance. It is also effective to add a Schottky diode if output has positive or negative great fluctuation when large current is used etc, for example, if counter electromotive voltage etc. is great. Moreover, in the output terminal, there is built-in clamp component for preventing of electrostatic destruction. If steep pulse or voltage of surge more than maximum absolute rating is applied, this clamp component operates, as a result there is the danger of even destruction, so please be sure that the maximum absolute rating must not be exceeded.

#### RNF1,RNF2 / Connection terminal of resistor for detecting of output current

Please connect the resistor of 0.1 ~ 0.3  $\Omega$  for current detection between this terminal and GND. In view of the power consumption of the current-detecting resistor, please determine the resistor in such a way that  $W=I_{OUT}^2 \cdot R[W]$  does not exceed the power dissipation of the resistor. In addition, please wire in such a way that it has a low impedance and does not have a impedance in common with other GND patterns because motor's drive current flows in the pattern through RNF terminal ~ current-detecting resistor ~ GND. Please do not exceed the rating because there is the possibility of circuits' malfunction etc. if RNF voltage has exceeded the maximum rating (0.7V). Moreover, please be careful because if RNF terminal is shorted to GND, large current flows without normal PWM constant current control, then there is the danger that OCP or TSD will operate. If RNF terminal is open, then there is the possibility of such malfunction as output current does not flow either, so please do not let it open.

#### RNF1S,RNF2S / Input terminal of current limit comparator

In this series, RNFS terminal, which is the input terminal of current limit comparator, is independently arranged in order to decrease the lowering of current-detecting accuracy caused by the wire impedance inside the IC of RNF terminal. Therefore, please be sure to connect RNF terminal and RNFS terminal together when using in the case of PWM constant current control. In addition, because the wires from RNFS terminal is connected near the current-detecting resistor in the case of interconnection, the lowering of current-detecting accuracy, which is caused by the impedance of board pattern between RNF terminal and the current-detecting resistor, can be decreased. Moreover, please design the pattern in such a way that there is no noise plunging. In addition, please be careful because if terminals of RNF1S & RNF2S are shorted to GND, large current flows without normal PWM constant current control and, then there is the danger that OCP or TSD will operate.

#### VREF / Output current value-setting terminal

This is the terminal to set the output current value. The output current value can be set by VREF voltage and current-detecting resistor (RNF resistor).

$$\text{Output current } I_{\text{OUT}} [\text{A}] = \{ \text{VREF} [\text{V}] / 5(\text{division ratio inside IC}) \} / \text{RNF} [\Omega]$$

Please avoid using it with VREF terminal open because if VREF terminal is open, the input is unsettled, and the VREF voltage increases, and then there is the possibility of such malfunctions as the setting current increases and a large current flows etc. Please keep to the input voltage range because if the voltage of over 3V is applied on VREF terminal, then there is also the danger that a large current flows in the output and so OCP or TSD will operate. Besides, please take into consideration the outflow current (max.2μA) if inputted by resistance division when selecting the resistance value. The minimum current, which can be controlled by VREF voltage, is determined by motor coil's L & R values and minimum ON time because there is a minimum ON time in PWM drive.

#### CR / Connection terminal of CR for setting chopping frequency

This is the terminal to set the chopping frequency of output. Please connect the external C(470p ~ 1500pF) and R(10k ~ 200k ) between this terminal and GND. Please refer to P9.

Please interconnect from external components to GND in such a way that the interconnection does not have impedance in common with other GND patterns. In addition, please carry out the pattern design in such ways as keeps such steep pulses as square wave etc. away and that there is no noise plunging. Please mount the two components of C and R if being used by PWM constant current control because normal PWM constant current control becomes impossible if CR terminal is open or it is biased externally.

#### MTH / Current decay mode-setting terminal

This is the terminal to set the current decay mode. Current decay mode can be optionally set according to input voltage.

MTH terminal input voltage [V]	Current decay mode
0~0.3	SLOW DECAY
0.4~1.0	MIX DECAY
1.5~3.5	FAST DECAY

Please connect to GND if using at SLOW DECAY mode.

Please avoid using with MTH terminal open because if MTH terminal is open, the input is unsettled, and then there is the danger that PWM operation becomes unstable. Besides, please take into consideration the outflow current (max.2μA) if inputted by resistance division when selecting the resistance value.

#### NC terminal

This terminal is unconnected electrically with IC internal circuit.

#### IC back metal

For HTSSOP-B28 package, the heat-radiating metal is mounted on IC's back side, and on the metal the heat-radiating treatment is performed when in use, which becomes the precondition to use, so please secure sufficiently the heat-radiating area by surely connecting by solder with the GND plane on the board and getting as wide GND pattern as possible. Please be careful because the allowable loss as shown in P.20 cannot be secured if not connected by solder. Moreover, the back side metal is shorted with IC chip's back side and becomes the GND potential, so there is the danger of malfunction and destruction if shorted with potentials other than GND, therefore please absolutely do not design patterns other than GND through the IC's back side.



## PWM Constant current control

### 1) Current control operation

When the output transistor is turned on, the output current increases, raising the voltage over the current sense resistor. When the voltage on the RNF pin reaches the voltage value set by the internal 2-bit DAC and the VREF input voltage, the current limit comparator engages and enters current decay mode. The output is then held off for a period of time determined by the RC time constant connected to the CR pin. The process repeats itself constantly for PWM operation.

### 2) Noise-masking function

In order to avoid misdetection of output current due to RNF spikes that may occur when the output turns ON, the IC employs an automatic current detection-masking period ( $t_{ONMIN}$ ), during which current detection is disabled immediately after the output transistor is turned on. This allows for constant-current drive without the need for an external filter. This noise-masking period defines the minimum ON-time for the motor output transistor.

### 3) CR Timer

The CR filter connected to the CR pin is repeatedly charged and discharged between the VCRH and VCRL levels. The output of the internal comparator is masked while charging from VCRL to VCRH in order to cancel noise. (As mentioned above, this period defines the minimum ON-time of the motor output transistor.) The CR terminal begins discharging once the voltage reaches VCRH. When the output current reaches the current limit during this period (i.e. RNF voltage reaches the decay trigger voltage), then the IC enters decay mode. The CR continues to discharge during this period until it reaches VCRL, at which point the IC output is switched back ON. The current output and CR pin begin charging simultaneously. The CR charge time ( $t_{ONMIN}$ ) and discharge time ( $t_{discharge}$ ) are set by external components, according to the following formulas. The total of  $t_{ONMIN}$  and  $t_{discharge}$  yield the chopping period,  $t_{chop}$ .

$$t_{ONMIN}[s] = C \cdot R' \cdot R / (R' + R) \cdot \ln[(VCR - 0.4)/(VCR - 1.0)]$$

$$VCR = V \cdot R / (R' + R)$$

V: internal regulator voltage 5V(Typ.)

R': CR terminal internal impedance 5k (Typ.)

$$t_{discharge}[s] = C \cdot R \cdot \ln[(1 + )/0.4]$$

:See the right graph.

$$t_{CHOP}[s] = t_{ONMIN} + t_{discharge}$$

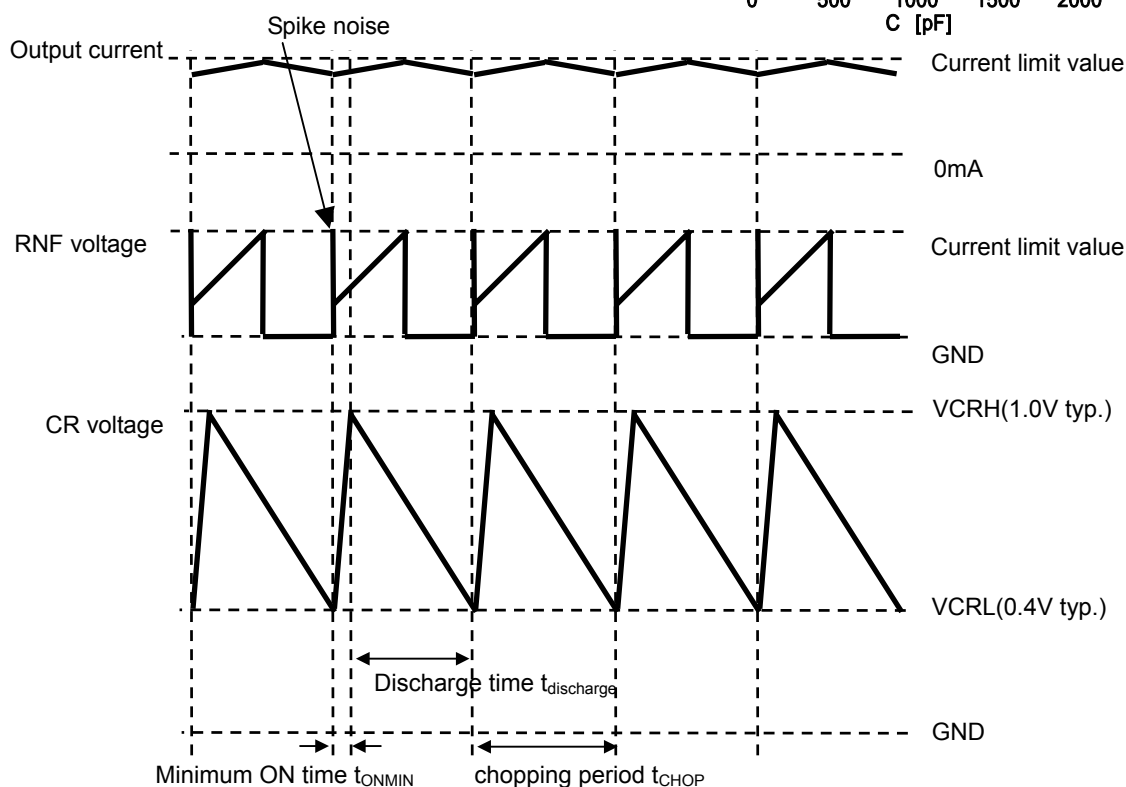
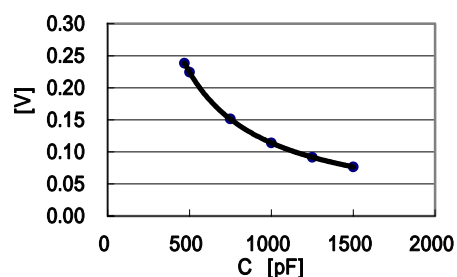


Fig.4 Timing chart of CR voltage, RNF voltage and output current

Attach a resistor of at least 10 kΩ to the CR terminal (10 kΩ~200 kΩ recommended) as lower values may keep the RC from reaching the VCRH voltage level. A capacitor in the range of 470 pF – 1500 pF is also recommended. As the capacitance value is increased, however, the noise-masking period ( $t_{onmin}$ ) also increases, and there is a risk that the output current may exceed the current limit threshold due to the internal L and R components of the output motor coil. Also, ensure that the chopping period ( $t_{chop}$ ) is not set longer than necessary, as doing so will increase the output ripple, thereby decreasing the average output current and yielding lower output rotation efficiency. The optimal value should reduce the motor drive noise while keeping distortion of the output current waveform to a minimum.

Current decay mode

The IC allows for a mixed decay mode in which the ratio of fast and slow decay can be optionally set.

The following diagrams show the operating state of each transistor and the regenerative current path during attenuation for each decay mode:

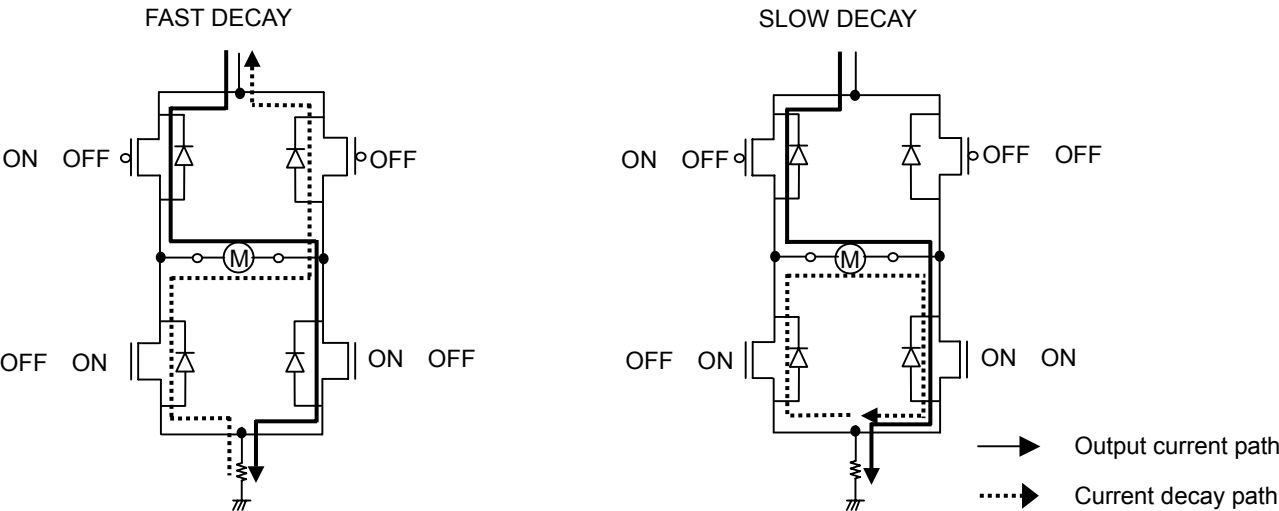


Fig.5 Route of regenerative current during current decay

The merits of each decay mode are as follows:

SLOW DECAY

During current attenuation, the voltage between motor coils is small and the regeneration current decreases slowly, decreasing the output current ripple. This is favorable for keeping motor torque high. However, due to fall-off of current control characteristics in the low-current region, or due to reverse EMF of the output motors exhibited when using high-pulse-rate half-step or quarter-step modes, the output current increases, distorting the output current waveform and increasing motor vibration. Thus, this decay mode is most suited to full-step modes, or low-pulse-rate half-step or quarter-step modes.

FAST DECAY

Fast decay decreases the regeneration current much more quickly than slow decay, greatly reducing distortion of the output current waveform. However, fast decay yields a much larger output current ripple, which decreases the overall average current running through the motor. This causes two problems: first, the motor torque decreases (increasing the current limit value can help eliminate this problem, but the rated output current must be taken into consideration); and second, the power loss within the motor increases and thereby radiates more heat. If neither of these problems is of concern, then fast decay can be used for high-pulse rate half- or quarter-step drive.

Additionally, this IC allows for a mixed decay mode that can help improve upon problems that arise from using fast or slow decay alone. In this mode, the IC switches automatically between slow and fast decay, improving the current control characteristics without increasing the output current ripple. The ratio of fast to slow decay is set externally via the voltage input to the MTH pin; therefore, the optimal mix of slow and fast decay can be achieved for each application. Mixed decay mode operates by splitting the decay period into two sections, the first  $X\%(t_1-t_2)$  of which operates the IC in slow decay mode, and the remainder  $(t_2-t_3)$  of which operates in fast decay mode. However, if the output current (i.e., the voltage on the RNF pin) does not reach the set current limit during the first  $X\%(t_1-t_2)$  decay period, the IC operates in fast decay mode only.

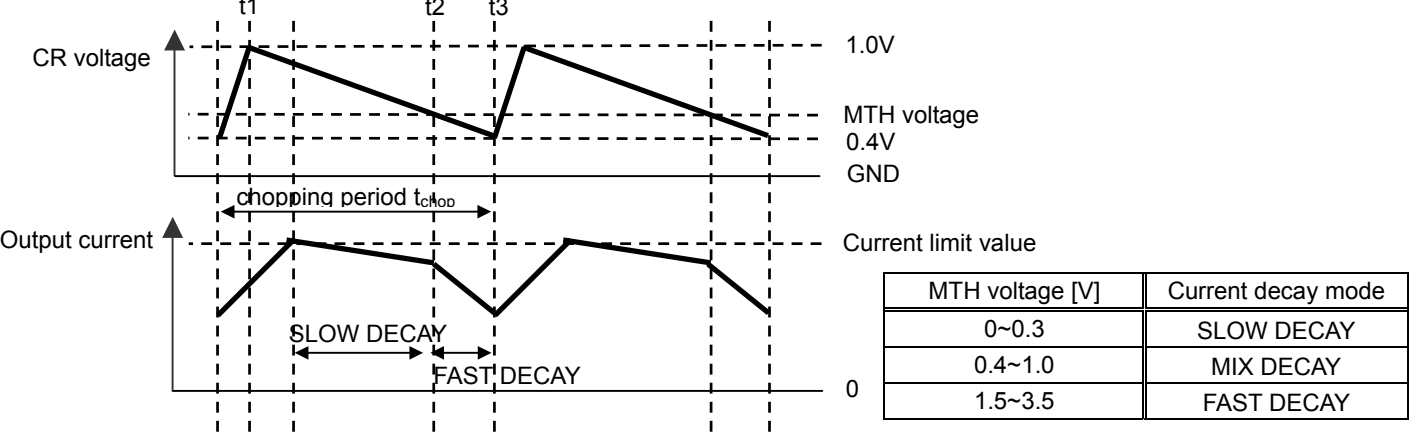


Fig.6 Relation between CR terminal voltage, MTH voltage, and output current during mixed decay

This series builds in translator circuit and can drive stepping motor in CLK-IN mode.

The operation of the translator circuit in CLK-IN drive mode is described as below.

### Reset operation

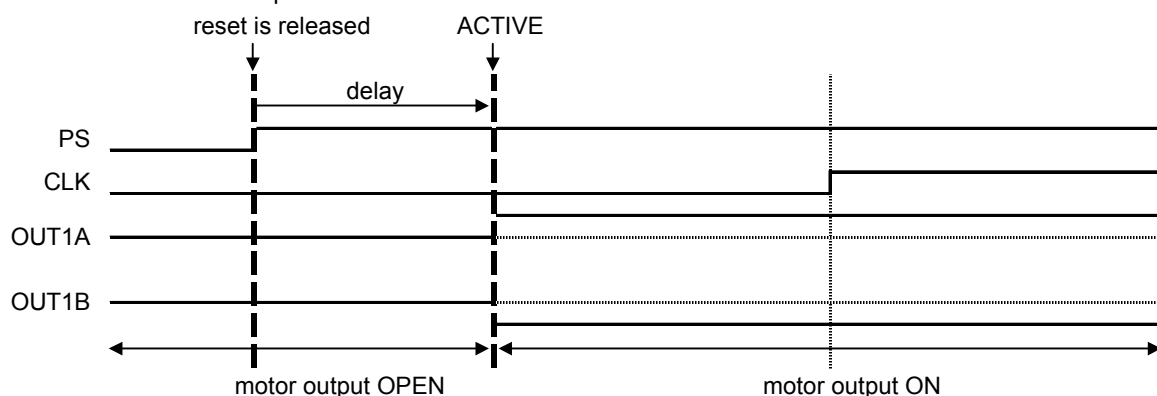
The translator circuit is initialized by power ON Reset function and PS terminal.

#### • Initializing operation when power supply is turned on

If power supply is turned on at PS=L (Please use this sequence as a general rule)

When power supply is turned on, the power ON reset function operates in IC and initialized, but as long as it is PS=L, the motor output is the OPEN state. After power supply is turned on, because of the changing of PS=L → H, the motor output become the ACTIVE state, and the excitation is started at the initial electrical angle.

But at the time of PS=L → H, it returns from the standby state to the normal state and there is a delay of 40 μs(max.) until the motor output has become the ACTIVE state.



If power supply is turned on at PS=H

When power supply is turned on, the power ON function in IC operates, and initialized before the motor output become the ACTIVE state, and the excitation is started at the initial electrical angle.

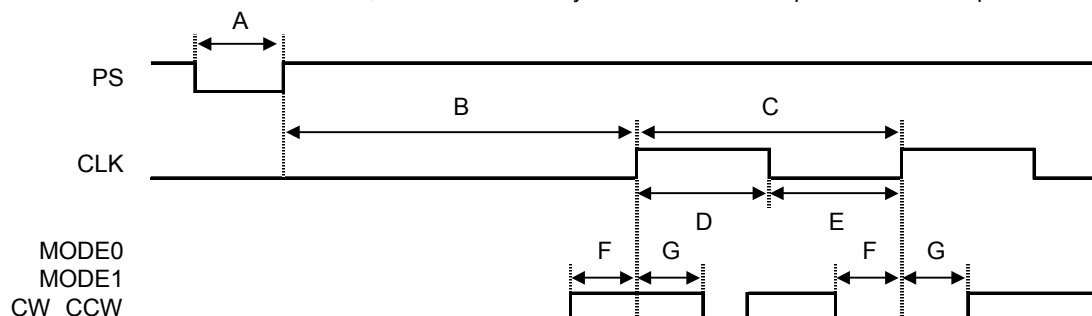
#### • Initializing operation during motor operating

Please input the reset signal to PS terminal when the translator circuit is initialized during motor operating. (Refer to P.14)

But at the time of PS=L → H, it returns from the standby state to the normal state and there is a delay of 40 μs (max.) until the motor output has become the ACTIVE state, so please be careful.

### Control input timing

Please input as shown below because the translator circuit operates at the rising edge of CLK signal. If you disobey this timing and input, then there is the possibility that the translator circuit does not operate as expected. In addition, at the time of PS=L → H, it returns from the standby state to the normal state and there is a delay of 40 μs (max.) until the motor output has become the ACTIVE state, so within this delay interval there is no phase advance operation even if CLK is inputted.



A:PS minimum input pulse width..... 20 μs

B:PS rising edge ~ CLK rising edge input possible maximum delay time..... 40 μs

C:CLK minimum period..... 4 μs

D:CLK minimum input H pulse width..... 2 μs

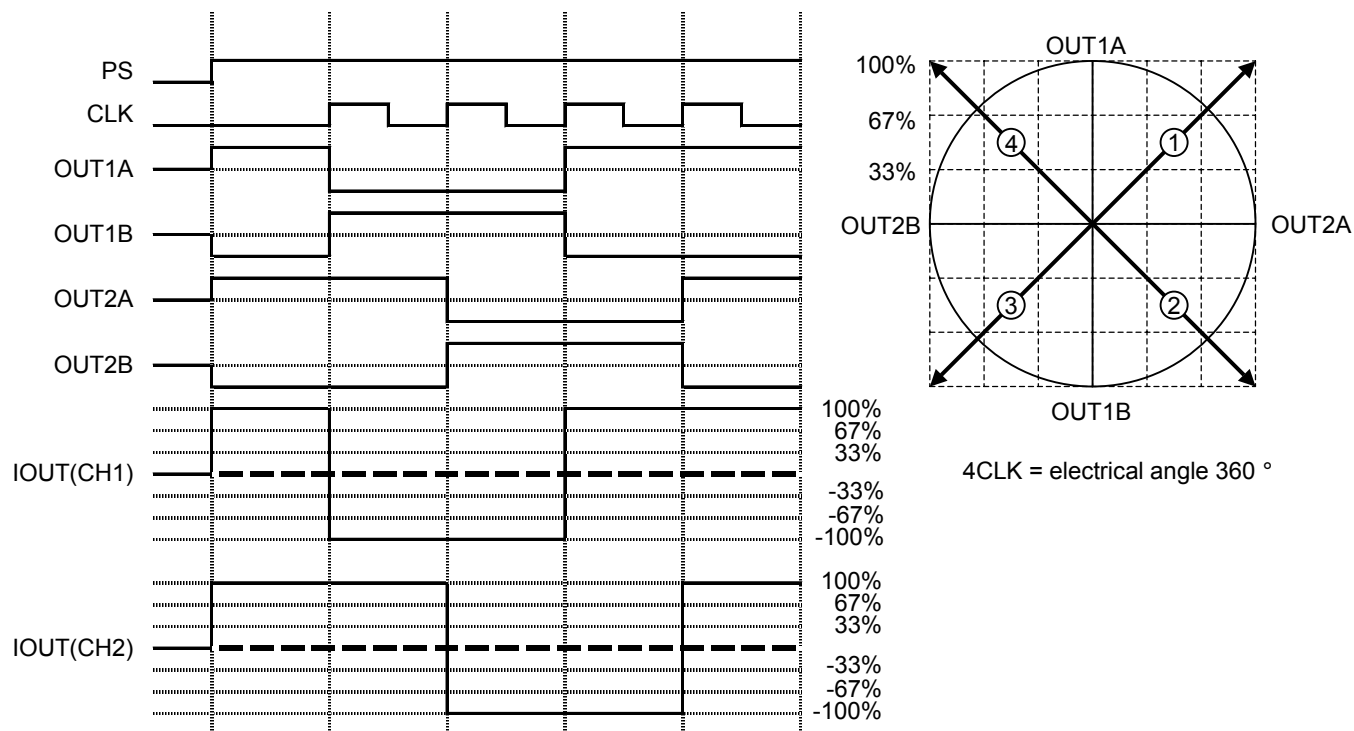
E:CLK minimum input L pulse width..... 2 μs

F:MODE0,MODE1,CW\_CCW set-up time..... 1 μs

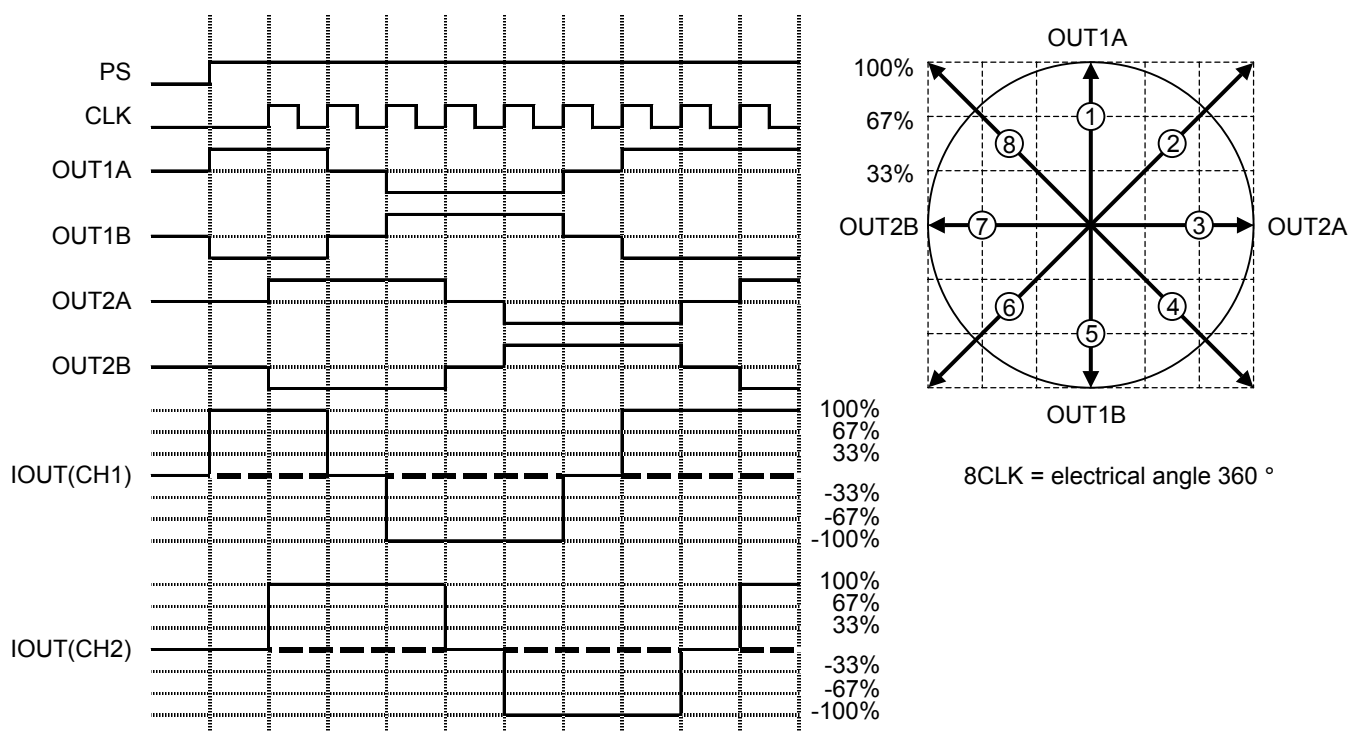
G:MODE0,MODE1,CW\_CCW hold time..... 1 μs

# Timing chart of CLK-IN drive mode (BD63877/BD63875/BD63873EFV)

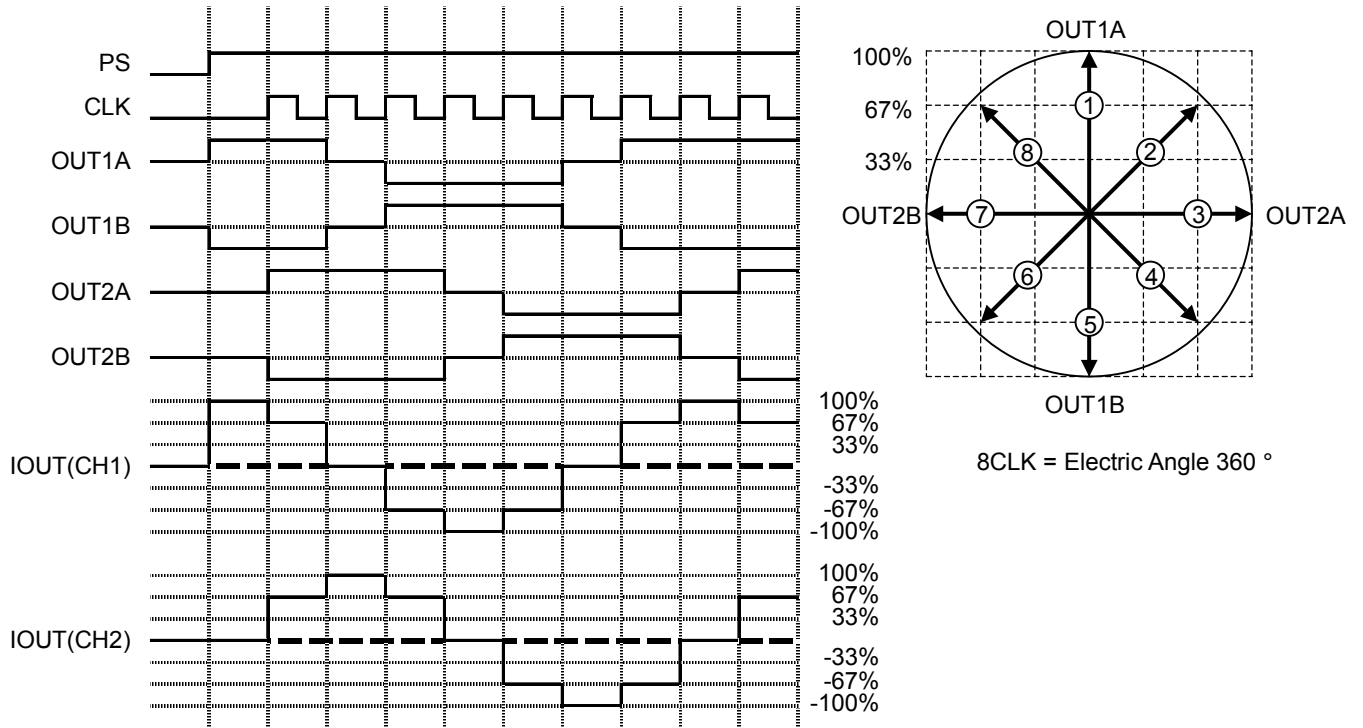
- FULL STEP (MODE0=L, MODE1=L, CW\_CCW=L, ENABLE=H)



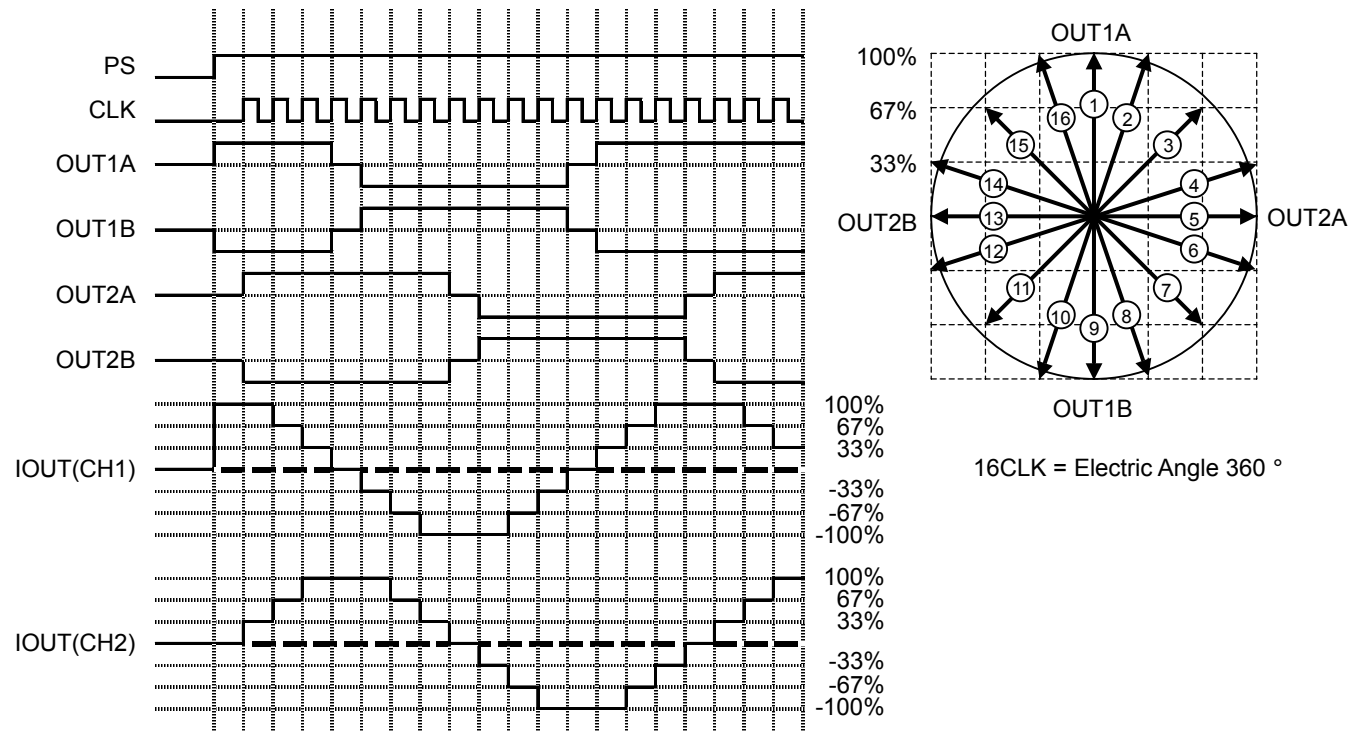
- HALF STEP A (MODE0=H, MODE1=L, CW\_CCW=L, ENABLE=H)



• HALF STEP B(MODE0=L, MODE1=H, CW\_CCW=L, ENABLE=H)

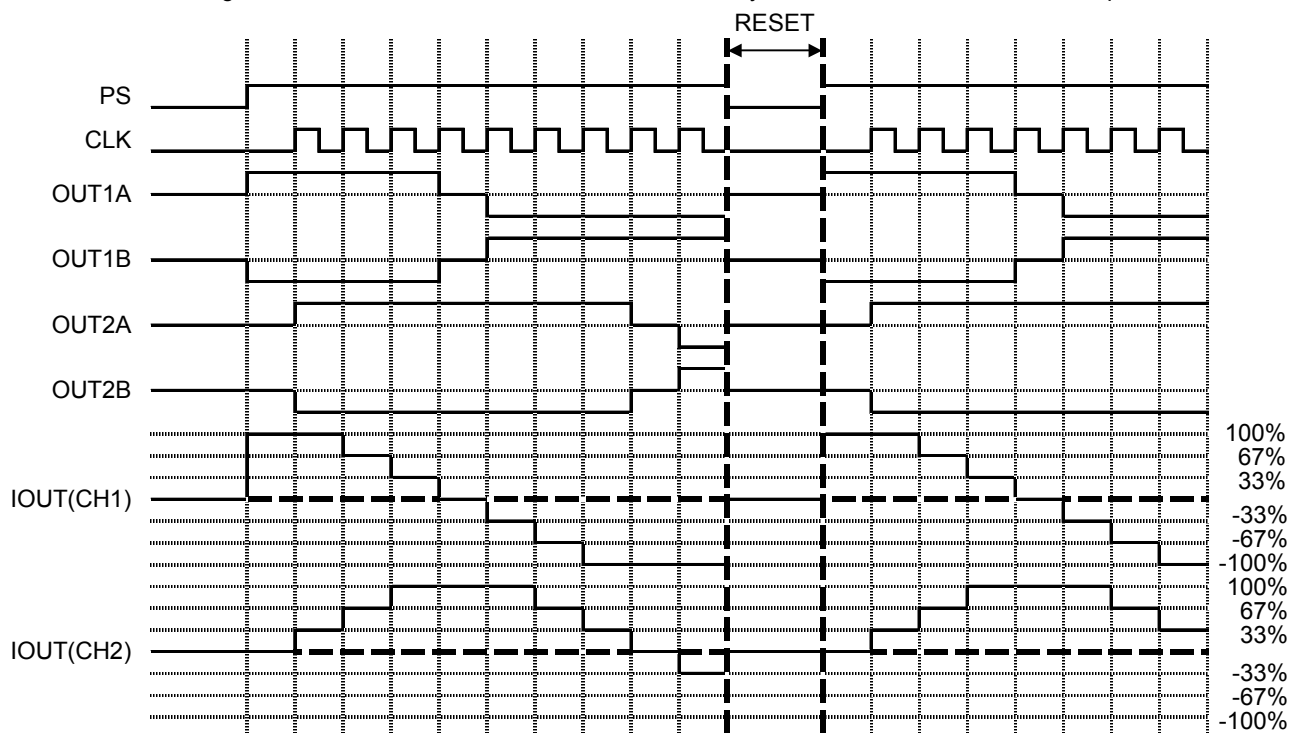


• QUARTER STEP(MODE0=H, MODE1=H, CW\_CCW=L, ENABLE=H)



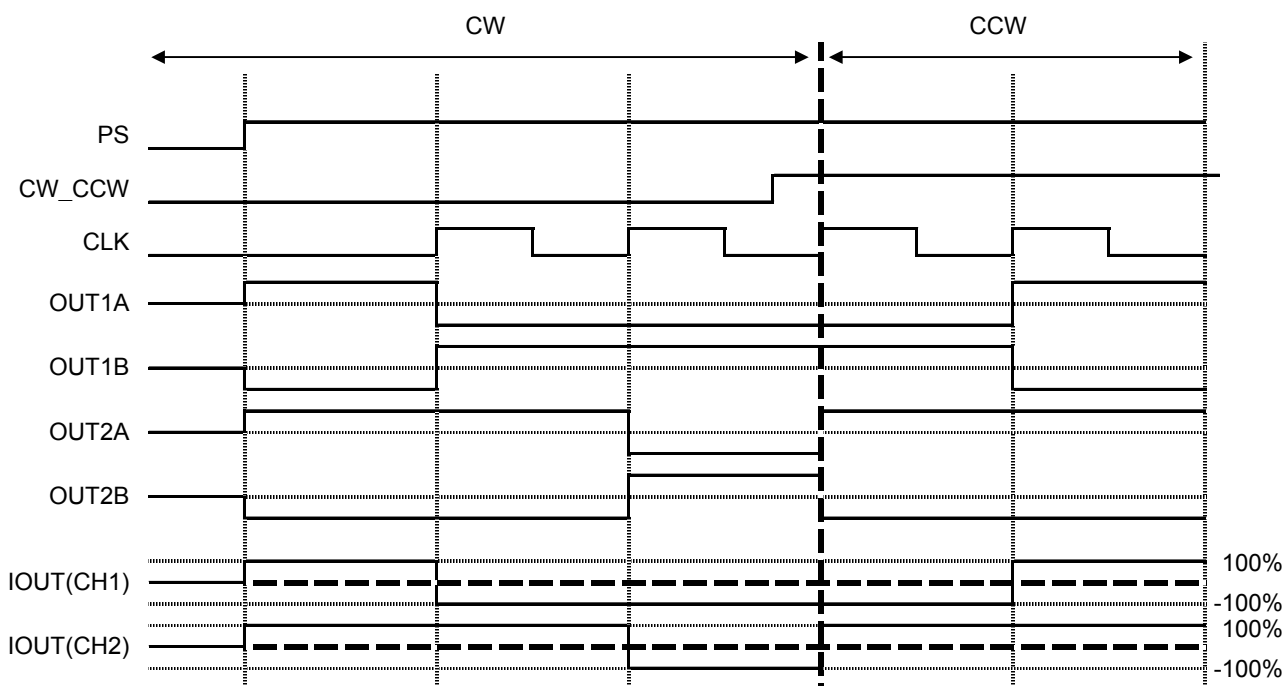
- Reset timing chart (QUARTER STEP, MODE0=H, MODE1=H, CW\_CCW=L , ENABLE=H)

If the terminal PS is input to L, the reset operation is done with regardless of other input signals when reset the translator circuit while motor is working. At this time, IC internal circuit enters the standby mode, and makes the motor output OPEN.



- CW\_CCW Switch timing chart (FULL STEP, MODE0=L, MODE1=L, ENABLE=H)

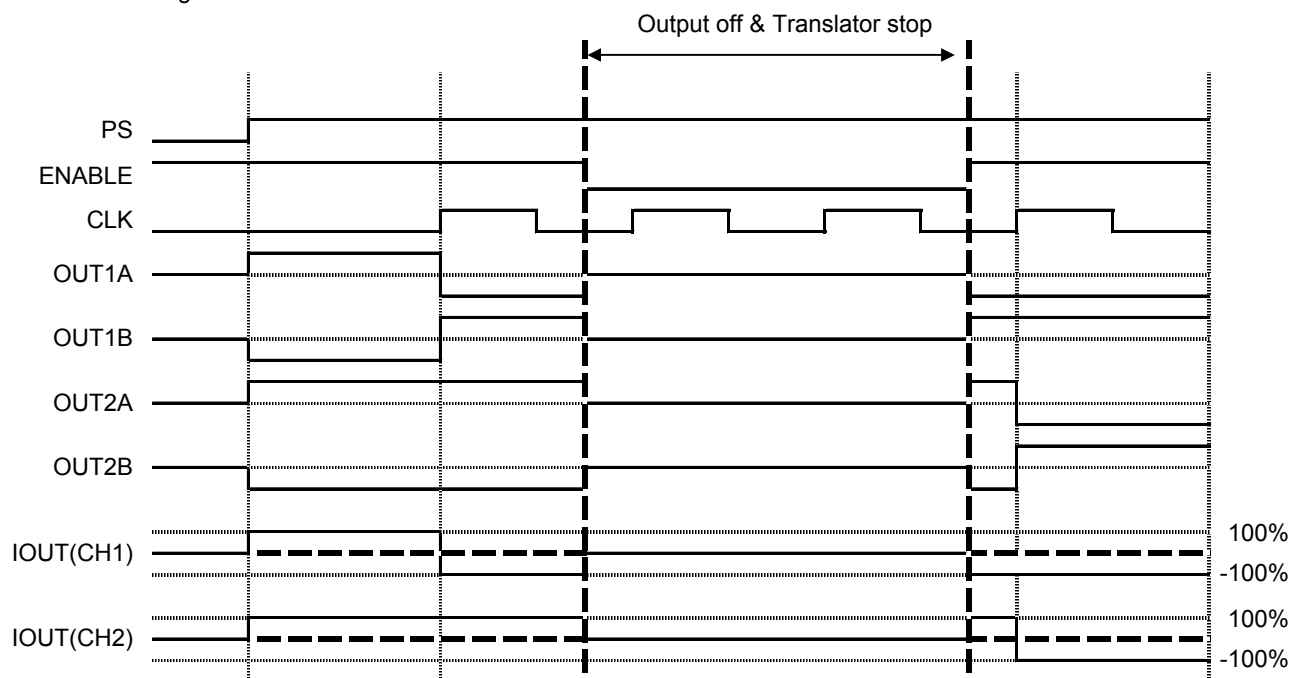
The switch of CW\_CCW is reflected by the rising edge of CLK that comes immediately after the changes of the CW\_CCW signal. However, depending on the state of operation of the motor at the switch the motor cannot follow even if the control on driver IC side is correspondent and there are possibilities of step-out and mistake step in motor, so please evaluate the sequence of the switch enough.



• ENABLE Switch timing chart (FULL STEP, MODE0=L, MODE1=L, ENABLE=H)

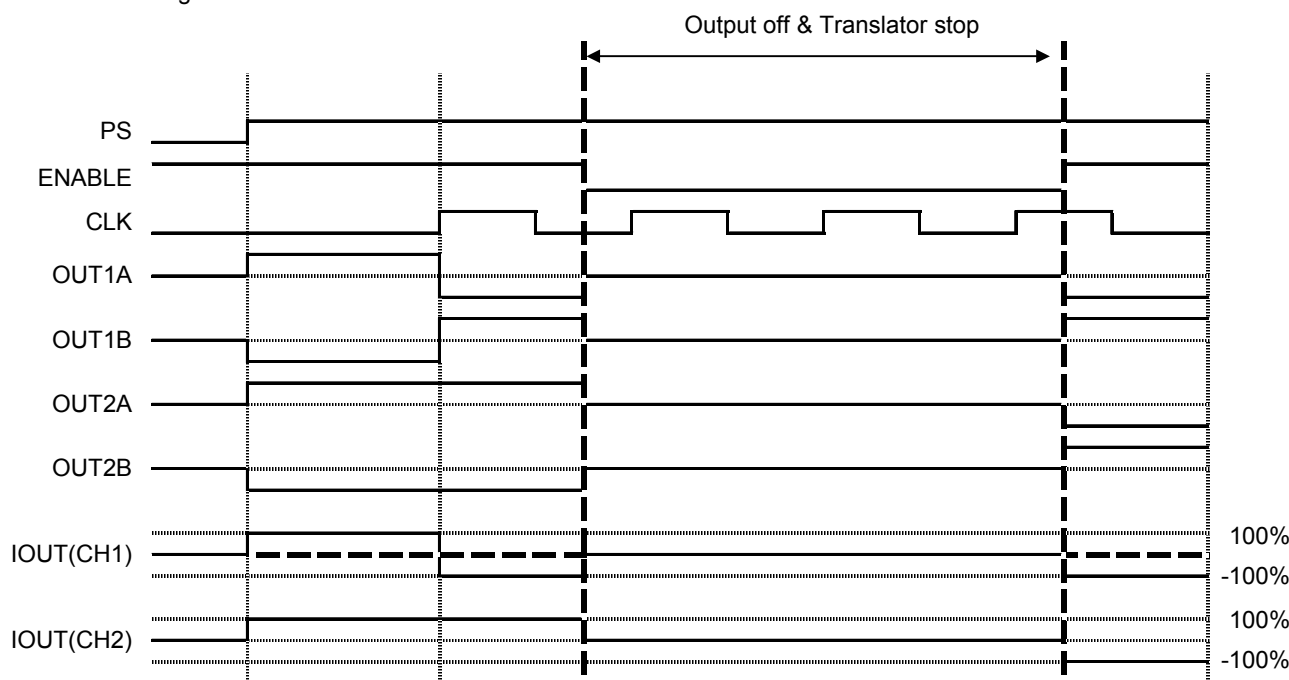
The switch of the ENABLE signal is reflected by the change in the ENABLE signal with regardless of other input signals. In the section of ENABLE=L, the motor output becomes OPEN and the electrical angle doesn't advance. Because the translator circuit stop and CLK input is canceled. Moreover, please note that the state of return is different when it returns in the CLK=H section or CLK=L section, returning to the state of ACTIVE by switching of ENABLE=L H.

When returning in the CLK=L section



It returns in the same state as the state before ENABLE=L is input.

When returning in the CLK=H section



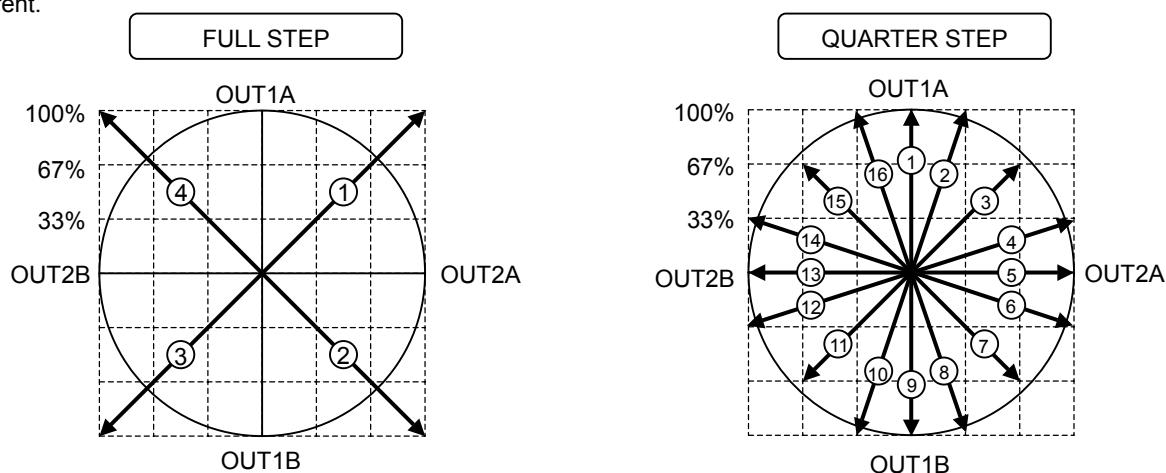
It returns in the following state of the state before ENABLE=L is input.

• About the switch of the motor excitation mode

Please usually switch the excitation mode in the state of PS=L and the electrical angle is reset. Please note the following points when it is not possible to switch unavoidably in the state of reset the switch of the excitation mode can be done with regardless of the CLK signal at the same time as changing of the signal MODE0 and MODE1, but has the possibility of the step-out and mistake step etc of the motor, because of the gap of the electric angle between the following each excitation modes before and after the mode switches according to the timing of the switch. Even if the control on driver IC side corresponds, the motor cannot follow depending on the state of operation of the motor at the switch, and there are possibilities of step-out and mistake step in motor, so please evaluate enough the switch sequence of the excitation mode and then make decision when you are in the application where the step-out and mistake step become a problem. The relation between the number of CLK pulses in each excitation mode and an electrical angle are shown as follows. The number in the table shows the position of the torque vector in each excitation mode of P.12 and 13.

CLK Number of pulses (n: Integer)	FULL STEP	HALF STEP A	HALF STEP B	QUARTER STEP
$0 + 16n$				
$1 + 16n$				
$2 + 16n$				
$3 + 16n$				
$4 + 16n$				
$5 + 16n$				
$6 + 16n$				
$7 + 16n$				
$8 + 16n$				
$9 + 16n$				
$10 + 16n$				
$11 + 16n$				
$12 + 16n$				
$13 + 16n$				
$14 + 16n$				
$15 + 16n$				

Please decide the switch timing of the signal MODE0 and MODE1 with the reference of above table when you switch the excitation mode. As an example, it thinks about time when it changes the excitation mode from FULL STEP to QUARTER STEP with the number of CLK pulses in the state of 10. The position of the torque vector in FULL STEP is when the number of CLK pulses are in the state of 10 from the above table and it will be when you change it into QUARTER STEP from this position. Then, the direction of the torque vector can be the same, and can be switched smoothly when paying attention to the torque vector of the figure below. At this time we should think about the time when it changes the excitation mode from FULL STEP to QUARTER STEP with the number of CLK pulses in the state of 11. The position of the torque vector in FULL STEP is with the number of CLK is in the state of 11, it becomes when you change it from this position into QUARTER STEP. At this time, step-out and mistake step might happen because the direction of the torque vector is different.



In the same way, the number of CLK that the direction of the torque vector is corresponding in each excitation mode is as follows.

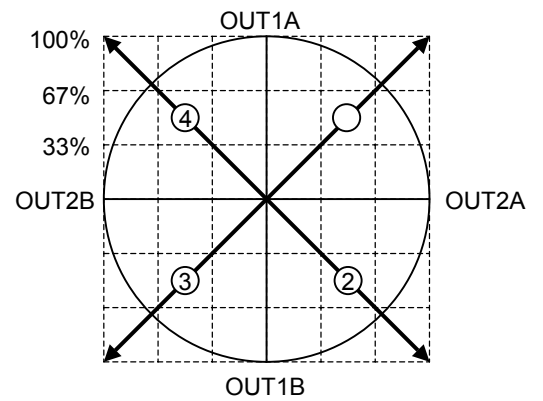
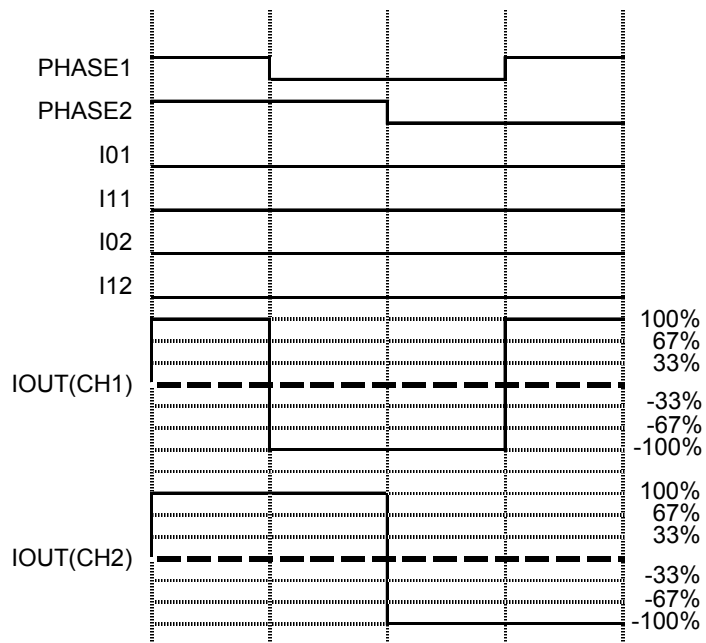
CLK Number of pulses (n: Integer)	FULL STEP	HALF STEP A	HALF STEP B	QUARTER STEP
$0 + 16n$	x			
$7 + 16n$				x
$10 + 16n$		x	x	



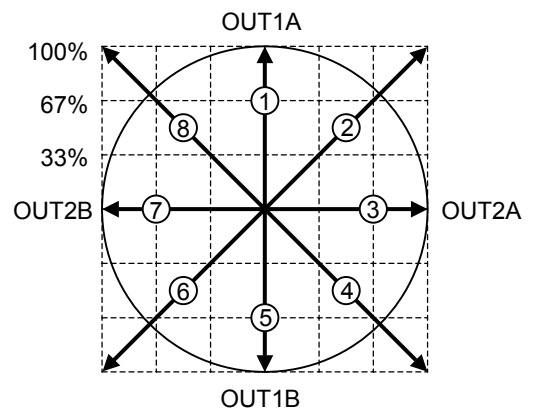
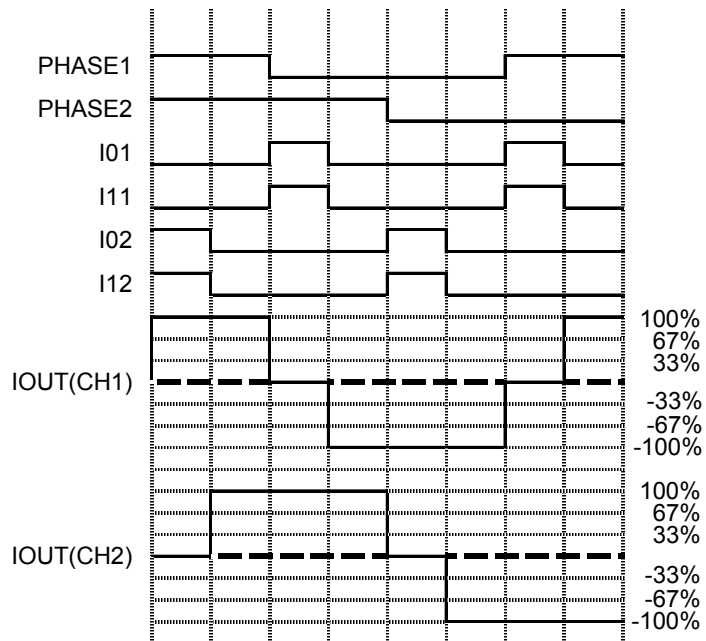
# Timing chart of PARALLEL-IN drive mode (BD63876/63874/63872EFV)

Example of control sequence and torque vector

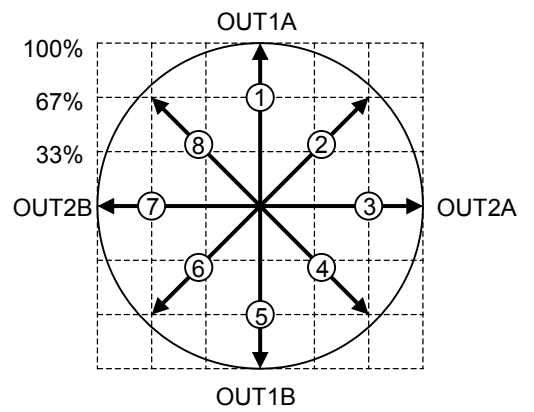
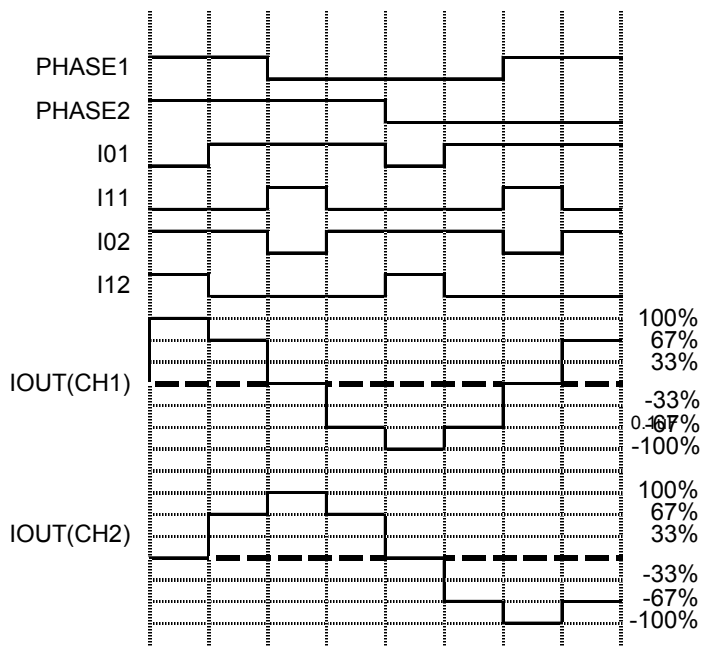
## FULL STEP



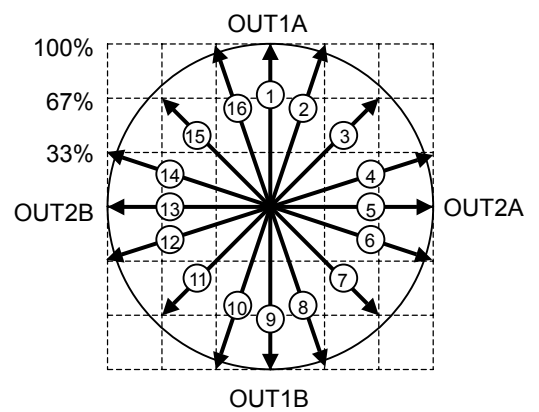
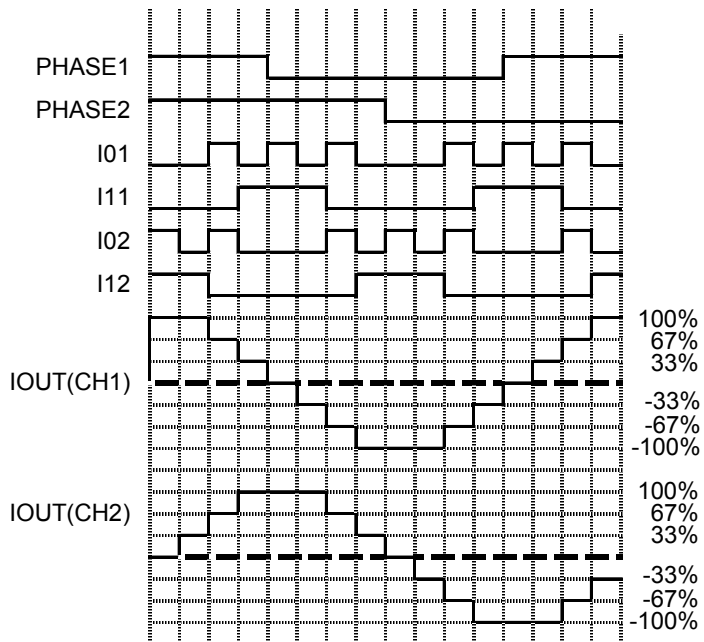
## HALF STEP A



## HALF STEP B



## QUARTER STEP



## Protection Circuits

### Thermal Shutdown (TSD)

This IC has a built-in thermal shutdown circuit for thermal protection. When the IC's chip temperature rises above 175 (Typ.), the motor output becomes OPEN. Also, when the temperature returns to under 150 (Typ.), it automatically returns to normal operation. However, even when TSD is in operation, if heat is continued to be added externally, heat overdrive can lead to destruction.

### Over Current Protection (OCP)

This IC has a built in over current protection circuit as a provision against destruction when the motor outputs are shorted each other or VCC-motor output or motor output-GND is shorted. This circuit latches the motor output to OPEN condition when the regulated threshold current flows for 4 $\mu$ s (Typ.). It returns with power reactivation or a reset of the PS terminal. The over current protection circuit's only aim is to prevent the destruction of the IC from irregular situations such as motor output shorts, and is not meant to be used as protection or security for the set. Therefore, sets should not be designed to take into account this circuit's functions. After OCP operating, if irregular situations continues and the return by power reactivation or a reset of the PS terminal is carried out repeatedly, then OCP operates repeatedly and the IC may generate heat or otherwise deteriorate. When the L value of the wiring is great due to the wiring being long, after the over current has flowed and the output terminal voltage jumps up and the absolute maximum values may be exceeded and as a result, there is a possibility of destruction. Also, when current which is over the output current rating and under the OCP detection current flows, the IC can heat up to over  $T_{jmax}=150$  and can deteriorate, so current which exceeds the output rating should not be applied.

### Under Voltage Lock Out (UVLO)

This IC has a built-in under voltage lock out function to prevent false operation such as IC output during power supply under voltage. When the applied voltage to the VCC terminal goes under 15V (Typ.), the motor output is set to OPEN. This switching voltage has a 1V (Typ.) hysteresis to prevent false operation by noise etc. Please be aware that this circuit does not operate during power save mode. Also, the electrical angle is reset when the UVLO circuit operates during CLK-IN drive mode.

### Over Voltage Lock Out (OVLO)

This IC has a built-in over voltage lock out function to protect the IC output and the motor during power supply over voltage. When the applied voltage to the VCC terminal goes over 32V (Typ.), the motor output is set to OPEN. This switching voltage has a 1V (Typ.) hysteresis and a 4 $\mu$ s (Typ.) mask time to prevent false operation by noise etc. Although this over voltage locked out circuit is built-in, there is a possibility of destruction if the absolute maximum value for power supply voltage is exceeded, therefore the absolute maximum value should not be exceeded. Please be aware that this circuit does not operate during power save mode.

### Ghost Supply Prevention (protects against malfunction when power supply is disconnected)

If a signal (logic input, VREF, MTH) is input when there is no power supplied to this IC, there is a function which prevents the false operation by voltage supplied via the electrostatic destruction prevention diode from these input terminals to the VCC to this IC or to another IC's power supply. Therefore, there is no malfunction of the circuit even when voltage is supplied to these input terminals while there is no power supply.

## Power dissipation

Please confirm that the IC's chip temperature  $T_j$  is not over 150 °C, while considering the IC's power consumption (W), package power ( $P_d$ ) and ambient temperature ( $T_a$ ). When  $T_j=150$  °C is exceeded the functions as a semiconductor do not operate and problems such as parasitism and leaks occur. Constant use under these circumstances leads to deterioration and eventually destruction of the IC.  $T_{jmax}=150$  °C must be strictly obeyed under all circumstances.

## Thermal Calculation

The IC's consumed power can be estimated roughly with the power supply voltage ( $V_{CC}$ ), circuit current ( $I_{CC}$ ), output ON resistance ( $R_{ONH}$ ,  $R_{ONL}$ ) and motor output current value ( $I_{OUT}$ ).

The calculation method during FULL STEP drive, SLOW DECAY mode is shown here:

Consumed power of the  $V_{CC}$  [W] =  $V_{CC}$  [V] ·  $I_{CC}$  [A] · · · · ·

Consumed power of the output DMOS [W] =  $\frac{(R_{ONH}[\Omega] + R_{ONL}[\Omega]) \cdot I_{OUT} [A]^2 \cdot 2[ch] \cdot on\_duty}{\text{During output ON}} + \frac{(2 \cdot R_{ONL}[\Omega]) \cdot I_{OUT} [A]^2 \cdot 2[ch] \cdot (1 - on\_duty)}{\text{During current decay}} \cdot \cdot \cdot \cdot$

However, on duty: PWM on duty =  $t_{on} / (t_{chop})$

$t_{on}$  varies depending on the L and R values of the motor coil and the current set value. Please confirm by actual measurement, or make an approximate calculation.

$t_{chop}$  is the chopping period, which depends on the external CR. See P.9 for details.

Model Number	Upper PchDMOS ON Resistance $R_{ONH}[\Omega]$ (Typ.)	Lower NchDMOS ON Resistance $R_{ONL}[\Omega]$ (Typ.)
BD63877/63876EFV	0.40	0.25
BD63875/63874EFV	0.60	0.40
BD63873/63872EFV	1.25	0.65

Consumed power of total IC  $W_{total}$  [W] = · +

Junction temperature  $T_j$  =  $T_a$  [°C] +  $\theta_{ja}$  [°C/W] ·  $W_{total}$  [W]

However, the thermal resistance value  $\theta_{ja}$  [°C/W] differs greatly depending on circuit board conditions. Refer to the derating curve on P.21. Also, we are taking measurements of thermal resistance value  $\theta_{ja}$  of boards actually in use. Please feel free to contact our salesman. The calculated values above are only theoretical. For actual thermal design, please perform sufficient thermal evaluation for the application board used, and create the thermal design with enough margin to not exceed  $T_{jmax}=150$  °C. Although unnecessary with normal use, if the IC is to be used under especially strict heat conditions, please consider externally attaching a Schottky diode between the motor output terminal and GND to abate heat from the IC.

## Temperature Monitoring

There is a way to directly measure the approximate chip temperature by using the TEST terminal (BD63877/BD63875/BD63873EFV) or low input I0X and I1X (BD63876/BD63874/BD63872EFV). However, temperature monitor using this TEST terminal is only for evaluation and experimenting, and must not be used in actual usage conditions. TEST terminal has a protection diode for prevention from electrostatic discharge. The temperature may be monitored using this protection diode.

- (1) Measure the terminal voltage when a current of  $I_{diode}=50\mu A$  flows from the TEST terminal to the GND, without supplying  $V_{CC}$  to the IC. This measurement is of the  $V_f$  voltage inside the diode.
- (2) Measure the temperature characteristics of this terminal voltage. ( $V_f$  has a linear negative temperature factor against the temperature.) With the results of these temperature characteristics, chip temperature may be calibrated from the TEST terminal voltage.
- (3) Supply  $V_{CC}$ , confirm the TEST terminal voltage while running the motor, and the chip temperature can be approximated from the results of (2).

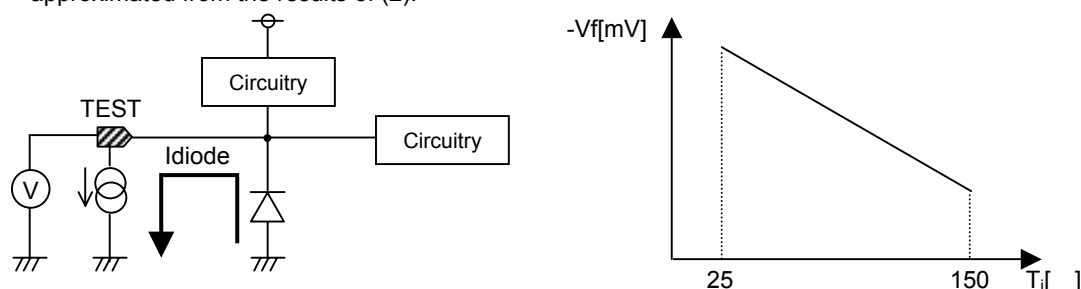


Fig.7 Model diagram for measuring chip temperature

## Power dissipation

### HTSSOP-B28 package

HTSSOP-B28 has exposed metal on the back, and it is possible to dissipate heat from a through hole in the back. Also, the back of board as well as the surfaces has large areas of copper foil heat dissipation patterns, greatly increasing power dissipation. The back metal is shorted with the back side of the IC chip, being a GND potential, therefore there is a possibility for malfunction if it is shorted with any potential other than GND, which should be avoided. Also, it is recommended that the back metal is soldered onto the GND to short. Please note that it has been assumed that this product will be used in the condition of this back metal performed heat dissipation treatment for increasing heat dissipation efficiency.

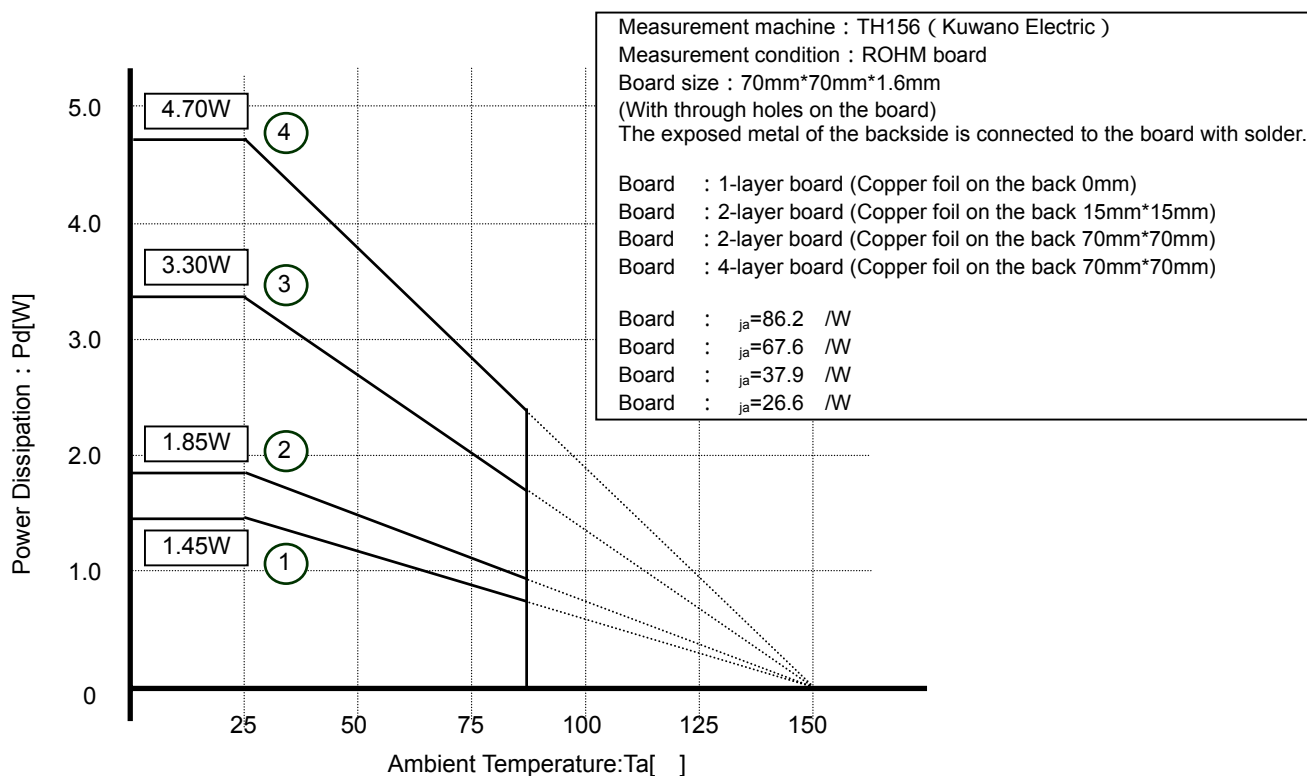


Fig.8 HTSSOP-B28 Derating Curve

## Usage Notes

### (1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

### (2) Connecting the power supply connector backward

Connecting of the power supply in reverse polarity can damage IC. Take precautions when connecting the power supply lines. An external direction diode can be added.

### (3) Power supply Lines

Design PCB layout pattern to provide low impedance GND and supply lines. To obtain a low noise ground and supply line, separate the ground section and supply lines of the digital and analog blocks. Furthermore, for all power supply terminals to ICs, connect a capacitor between the power supply and the GND terminal. When applying electrolytic capacitors in the circuit, not that capacitance characteristic values are reduced at low temperatures.

### (4) GND Potential

The potential of GND pin must be minimum potential in all operating conditions.

### (5) Metal on the backside (Define the side where product markings are printed as front)

The metal on the backside is shorted with the backside of IC chip therefore it should be connected to GND. Be aware that there is a possibility of malfunction or destruction if it is shorted with any potential other than GND.

### (6) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation ( $P_d$ ) in actual operating conditions. Users should be aware that these products have been designed to expose their frames at the back of the package, and should be used with suitable heat dissipation treatment in this area to improve dissipation. As large a dissipation pattern should be taken as possible, not only on the front of the baseboard but also on the back surface. It is important to consider actual usage conditions and to take as large a dissipation pattern as possible.

### (7) Inter-pin shorts and mounting errors

When attaching to a printed circuit board, pay close attention to the direction of the IC and displacement. Improper attachment may lead to destruction of the IC. There is also possibility of destruction from short circuits which can be caused by foreign matter entering between outputs or an output and the power supply or GND.

### (8) Operation in a strong electric field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

### (9) ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

### (10) Thermal shutdown circuit

The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes  $T_{jmax}=150$  , and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.

TSD on temperature [ ] (Typ.)	Hysteresis Temperature [ ] (Typ.)
175	25

### (11) Inspection of the application board

During inspection of the application board, if a capacitor is connected to a pin with low impedance there is a possibility that it could cause stress to the IC, therefore an electrical discharge should be performed after each process. Also, as a measure against electrostatic discharge, it should be earthed during the assembly process and special care should be taken during transport or storage. Furthermore, when connecting to the jig during the inspection process, the power supply should first be turned off and then removed before the inspection.

## (12) Input terminal of IC

This IC is a monolithic IC, and between each element there is a P+ isolation for element partition and a P substrate. This P layer and each element's N layer make up the P-N junction, and various parasitic elements are made up.

For example, when the resistance and transistor are connected to the terminal as shown in figure A,

When  $GND > (\text{Terminal A})$  at the resistance and  $GND > (\text{Terminal B})$  at the transistor (NPN), the P-N junction operates as a parasitic diode.

Also, when  $GND > (\text{Terminal B})$  at the transistor (NPN)

The parasitic NPN transistor operates with the N layers of other elements close to the aforementioned parasitic diode.

Because of the IC's structure, the creation of parasitic elements is inevitable from the electrical potential relationship. The operation of parasitic elements causes interference in circuit operation, and can lead to malfunction and destruction. Therefore, be careful not to use it in a way which causes the parasitic elements to operate, such as by applying voltage that is lower than the GND (P substrate) to the input terminal.

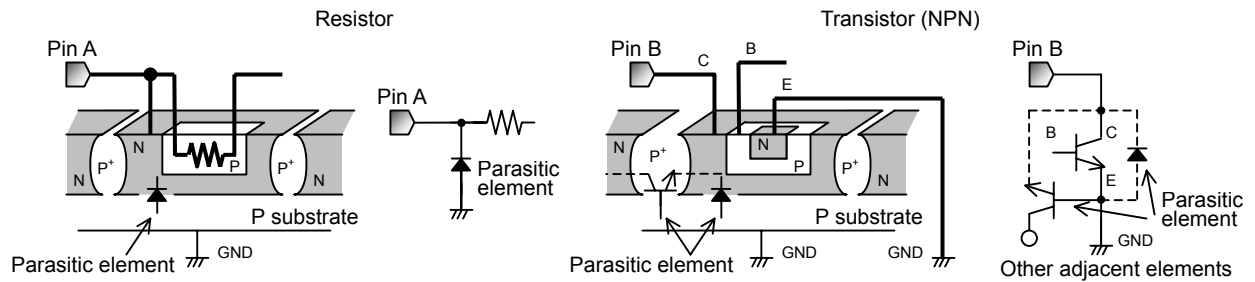


Fig. A Pattern Diagram of Parasitic Element

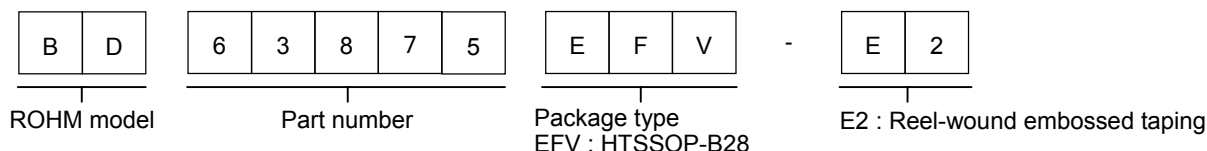
## (13) Ground Wiring Patterns

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the application's reference point so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern potential of any external components, either.

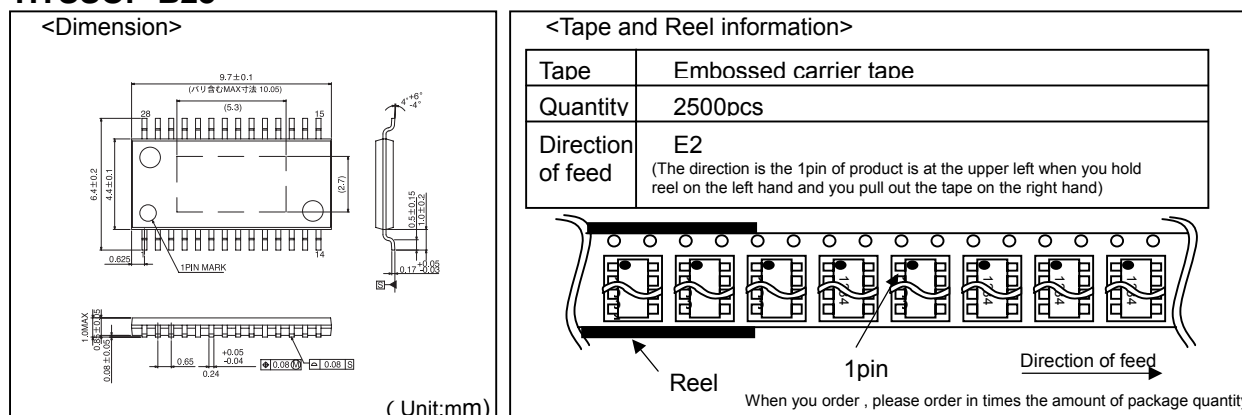
## (14) TEST Terminal (BD63877/BD63875/BD63873EFV)

Be sure to connect TEST pin to GND.

## Selecting a model name when ordering



## HTSSOP-B28



The content specified in this document is correct as of **1st , 2009, January**

No copying or reproduction of this document, in part or in whole, is permitted without the consent of ROHM CO.,LTD.

The content specified herein is subject to change for improvement without notice.

The content specified herein is for the purpose of introducing ROHM's products (hereinafter "Products"). If you wish to use any such Product, please be sure to refer to the specifications, which can be obtained from ROHM upon request.

Examples of application circuits, circuit constants and any other information contained herein illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

Great care was taken in ensuring the accuracy of the information specified in this document. However, should you incur any damage arising from any inaccuracy or misprint of such information, ROHM shall bear no responsibility for such damage.

The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM and other parties. ROHM shall bear no responsibility whatsoever for any dispute arising from the use of such technical information.

The Products specified in this document are intended to be used with general-use electronic equipment or devices (such as audio visual equipment, office-automation equipment, communication devices, electronic appliances and amusement devices).

The Products are not designed to be radiation tolerant.

While ROHM always makes efforts to enhance the quality and reliability of its Products, a Product may fail or malfunction for a variety of reasons.

Please be sure to implement in your equipment using the Products safety measures to guard against the possibility of physical injury, fire or any other damage caused in the event of the failure of any Product, such as derating, redundancy, fire control and fail-safe designs. ROHM shall bear no responsibility whatsoever for your use of any Product outside of the prescribed scope or not in accordance with the instruction manual.

The Products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability the failure or malfunction of which may result in a direct threat to human life or create a risk of human injury (such as a medical instrument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel-controller or other safety device). ROHM shall bear no responsibility in any way for use of any of the Products for the above special purposes. If a Product is intended to be used for any such special purpose, please contact a ROHM sales representative before purchasing.

If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.

## ROHM Sales Offices

Contact us for further information about the products.

RO128A

<b>San Diego</b>	+1-858-625-3630	<b>United Kingdom</b>	+44-1-908-272400	<b>Tianjin</b>	+86-22-23029181	<b>Xiamen</b>	+86-592-238-5705
<b>Atlanta</b>	+1-770-754-5972	<b>Denmark</b>	+45-3694-4739	<b>Shanghai</b>	+86-21-6279-2727	<b>Zhuhai</b>	+86-756-3232-480
<b>Boston</b>	+1-978-371-0382	<b>Espoo</b>	+358-9725-54491	<b>Hangzhou</b>	+86-571-87658072	<b>Hong Kong</b>	+852-2-740-6262
<b>Chicago</b>	+1-847-368-1006	<b>Salo</b>	+358-2-7332234	<b>Nanjing</b>	+86-25-8689-0015	<b>Taipei</b>	+886-2-2500-6956
<b>Dallas</b>	+1-972-473-3748	<b>Oulu</b>	+358-8-5372930	<b>Ningbo</b>	+86-574-87654201	<b>Kaohsiung</b>	+886-7-237-0881
<b>Denver</b>	+1-303-708-0908	<b>Barcelona</b>	+34-9375-24320	<b>Qingdao</b>	+86-532-8577-9312	<b>Singapore</b>	+65-6332-2322
<b>Detroit</b>	+1-248-348-9920	<b>Hungary</b>	+36-1-4719338	<b>Suzhou</b>	+86-512-6807-1300	<b>Philippines</b>	+63-2-807-6872
<b>Nashville</b>	+1-615-620-6700	<b>Poland</b>	+48-22-5757213	<b>Wuxi</b>	+86-510-82702693	<b>Thailand</b>	+66-2-254-4890
<b>Mexico</b>	+52-33-3123-2001	<b>Russia</b>	+7-495-739-41-74	<b>Guangzhou</b>	+86-20-3878-8100	<b>Kuala Lumpur</b>	+60-3-7958-8355
<b>Düsseldorf</b>	+49-2154-9210	<b>Seoul</b>	+82-2-8182-700	<b>Penang</b>	+86-752-205-1054	<b>Penang</b>	+60-4-2286453
<b>Munich</b>	+49-8999-216168	<b>Masan</b>	+82-55-240-6234	<b>Fuzhou</b>	+86-591-8801-8698	<b>Kyoto</b>	+81-75-365-1218
<b>Stuttgart</b>	+49-711-7272-370	<b>Dalian</b>	+86-411-8230-8549	<b>Dongguan</b>	+86-769-8393-3320	<b>Yokohama</b>	+81-45-476-2290
<b>France</b>	+33-1-5697-3060	<b>Beijing</b>	+86-10-8525-2483	<b>Shenzhen</b>	+86-755-8307-3008		

Catalog No.09T000A '09.1 ROHM © 1000 NZ Published by LSI Business Promotion Group

## ROHM Co., Ltd.

21 Sain Mizosaki-cho, Ukyo-ku,  
Kyoto 615-8585 Japan  
TEL : +81-75-311-2121 FAX : +81-75-315-0172

www.rohm.com

